

MODEL NAME : QAZA0  
PCB NO : LA-8821P ( DAB00000B00 )

BOM P/N :

- 4619J831L01 -> i5, 1.7G, DDR3L-4GB
- 4619J831L02 -> i5, 1.7G, DDR3L-8GB
- 4619J831L03 -> i7, 1.9G, DDR3L-4GB
- 4619J831L04 -> i7, 1.9G, DDR3L-8GB
- 4619J831L06 -> i5, 1.8G, DDR3L-4GB
- 4619J831L07 -> i5, 1.8G, DDR3L-8GB
- 4619J831L08 -> i7, 2.0G, DDR3L-4GB
- 4619J831L09 -> i7, 2.0G, DDR3L-8GB
- 4619J831L10 -> i5, 1.8G, DDR3L-4GB-NT
- 4619J831L11 -> i5, 1.8G, DDR3L-8GB-NT
- 4619J831L12 -> i7, 2.0G, DDR3L-4GB-NT
- 4619J831L13 -> i7, 2.0G, DDR3L-8GB-NT
- 4619J831L14 -> i5, 1.7G, DDR3L-4GB-NT
- 4619J831L15 -> i5, 1.7G, DDR3L-8GB-NT
- 4619J831L16 -> i7, 1.9G, DDR3L-4GB-NT
- 4619J831L17 -> i7, 1.9G, DDR3L-8GB-NT

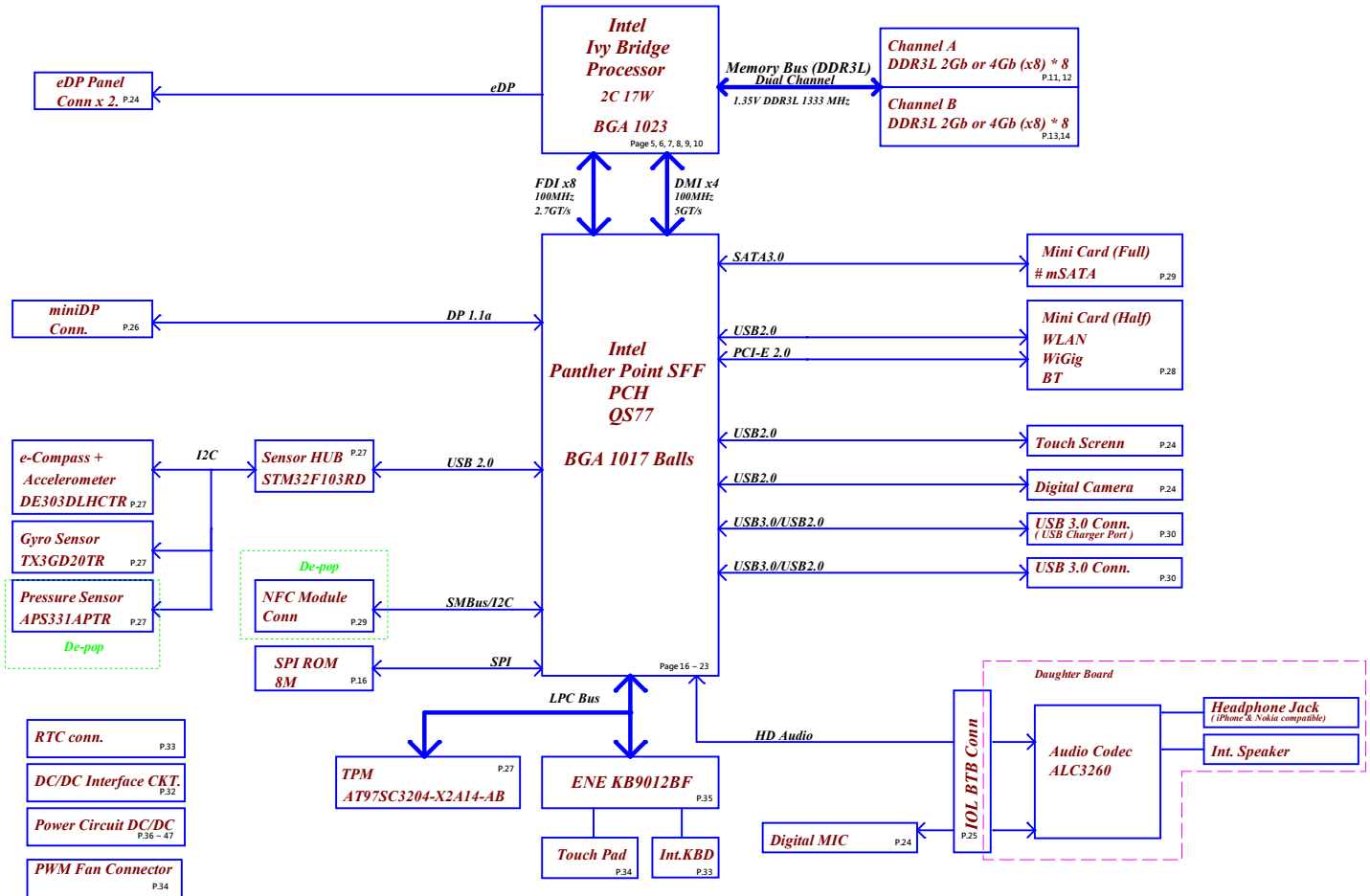
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## Schematic Document

Murcielgo (Chief River SFF)  
Ivy Bridge(BGA) + Panther Point(SFF, QS77)

2012-08-21  
Rev: 1.0

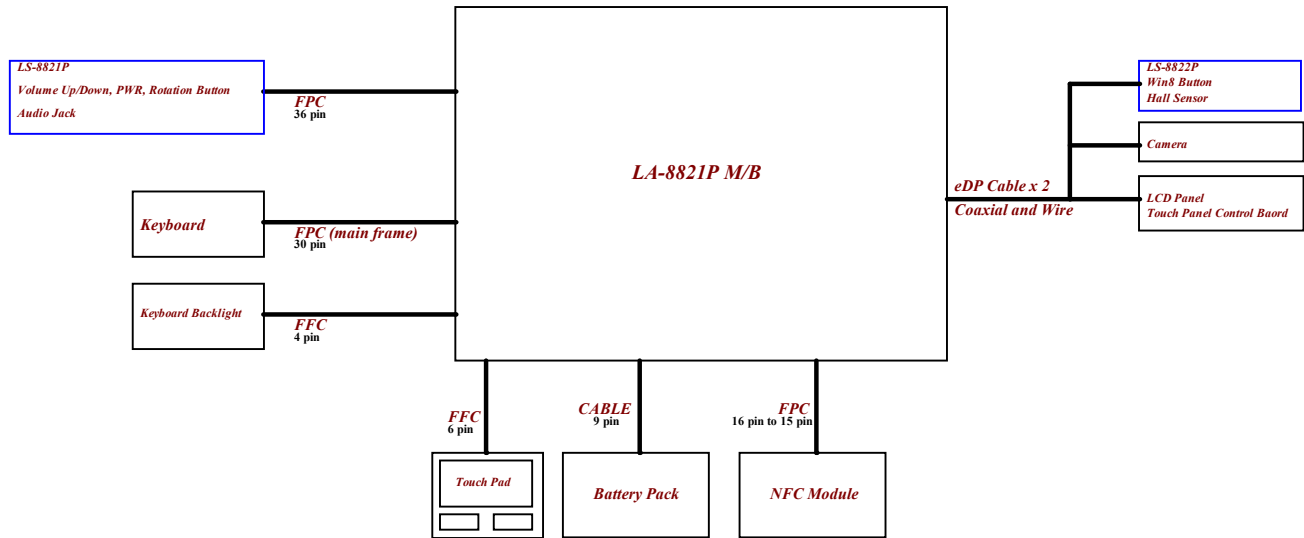
Highlight the short pad for 0 ohm



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Issued Date	2011/02/23	Deciphered Date	2013/10/28	Title	P02-Block Diagram
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Project Code : QAZA0  
File Name : LA-8821P



Board ID Table for AD channel

Vcc		3.3V +/- 5%			
Ra		100K +/- 5%			
Board ID	Rb	V <sub>AD, no</sub> min	V <sub>AD, no</sub> typ	V <sub>AD, no</sub> max	EC AD3
0	0	0 V	0 V	0.155 V	0x00-0x0C
1	8.2K +/- 5%	0.168 V	0.250 V	0.362 V	0x0D-0x1C
2	18K +/- 5%	0.375 V	0.503 V	0.621 V	0x1D-0x30
3	33K +/- 5%	0.634 V	0.819 V	0.945 V	0x31-0x49
4	56K +/- 5%	0.958 V	1.185 V	1.359 V	0x4A-0x69
5	100K +/- 5%	1.372 V	1.650 V	1.838 V	0x6A-0x8E
6	200K +/- 5%	1.851 V	2.200 V	2.420 V	0x8F-0xBB
7	NC	2.433 V	3.300 V	3.300 V	0xBB-0xFF

BOARD ID Table

Board ID	PCB Revision
0	0.1 Non Deep S3
1	0.1 Deep S3
2	0.2 (X01)
3	0.4 (X02)
4	1.0 (A00)
5	
6	
7	

SMBUS Control Table

	SOURCE	WLAN	BATT	Charger	NFC	Touch Pad	DDR3 SPD	ALS
EC_SMB_CLK1 EC_SMB_CLK1	KB930		V	V				
EC_SMB_CLK2 EC_SMB_CLK2	KB930							V
PCH_SMBCLK PCH_SMBCLKDATA	PCH				V			
PCH_SMBCLK PCH_SMBCLKDATA	PCH							
MEM_SMBCLK MEM_SMBCLKDATA	PCH	V				V	V	

Link

PCH  
USB  
Port  
Mapping

USB PORT#	DESTINATION
0	External USB3
1	External USB3
2	
3	
4	MINI CARD-1 WLAN
5	
6	
7	
8	
9	Touch Panel
10	
11	
12	Camera
13	Sensor HUB

PCH  
DDI  
Port  
Mapping

DDI PORT#	DESTINATION
B	
C	
D	mini-DP

CLK	DIFFERENTIAL	DESTINATION	FLEX CLOCKS	DESTINATION
	CLKOUT_PCIE0		CLKOUTFLEX0	TPM
	CLKOUT_PCIE1		CLKOUTFLEX1	
	CLKOUT_PCIE2		CLKOUTFLEX2	
	CLKOUT_PCIE3	MINI CARD-1 WLAN	CLKOUTFLEX3	
	CLKOUT_PCIE4		PCI CLKOUT	DESTINATION
	CLKOUT_PCIE5		PCI0	PCH_LOOPBACK
	CLKOUT_PCIE6		PCI1	EC LPC
	CLKOUT_PCIE7		PCI2	
	CLKOUT_PEG_B		PCI3	
			PCI4	

SATA	DESTINATION
SATA0	m-SATA
SATA1	
SATA2	
SATA3	
SATA4	
SATA5	

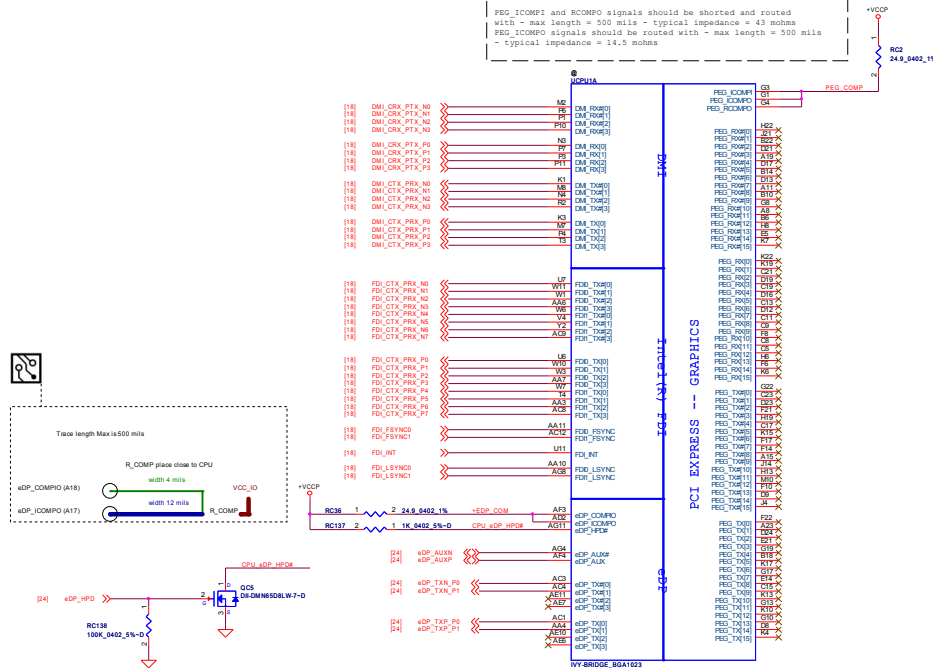
PCI EXPRESS	DESTINATION
Lane 1	
Lane 2	
Lane 3	MINI CARD-1 WLAN
Lane 4	
Lane 5	
Lane 6	
Lane 7	
Lane 8	

Symbol Note :

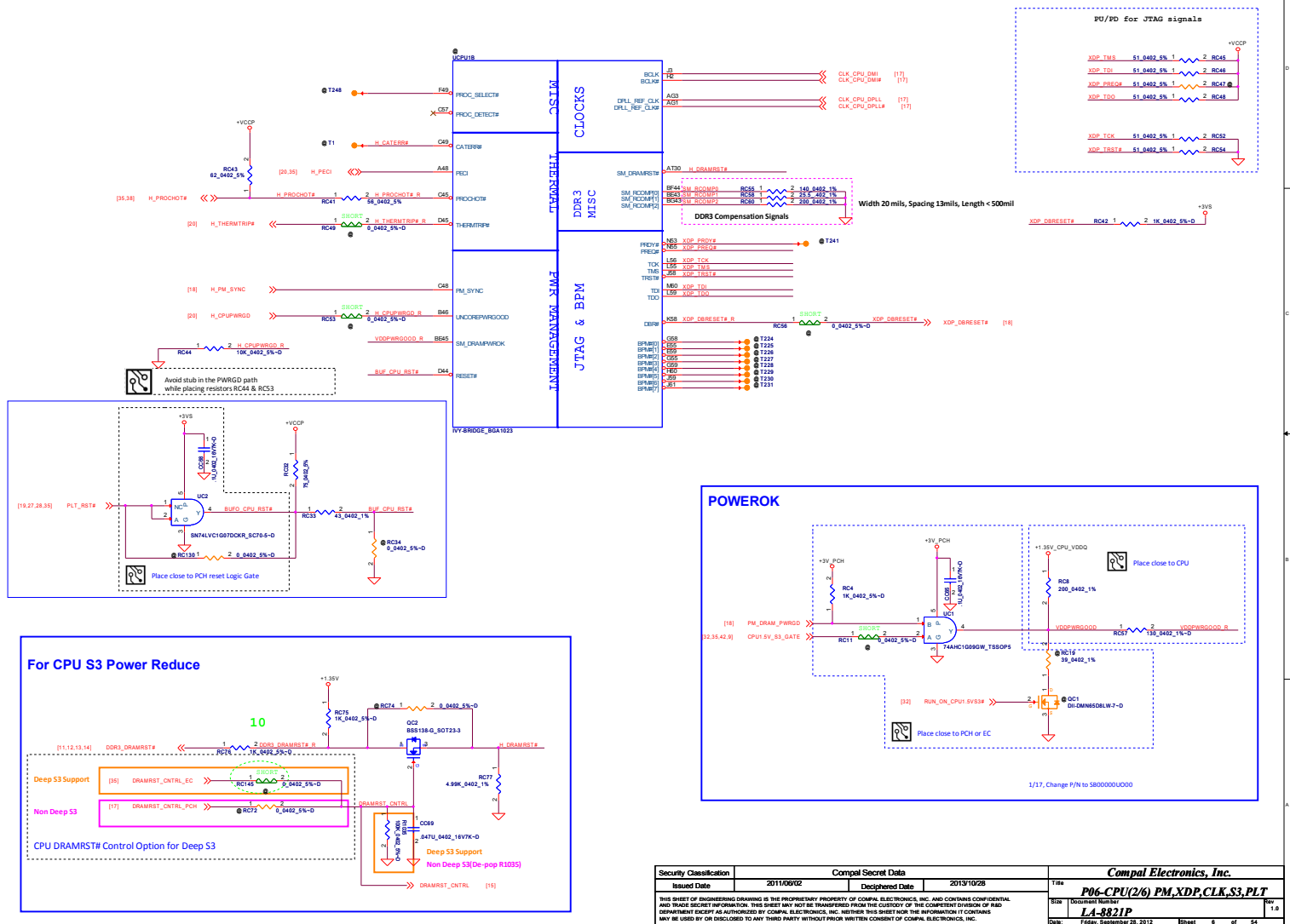
 : means Digital Ground

 : means Analog Ground

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1.4-8821P				Rev	1.0
Date: February 28, 2012				Sheet	4 of 50

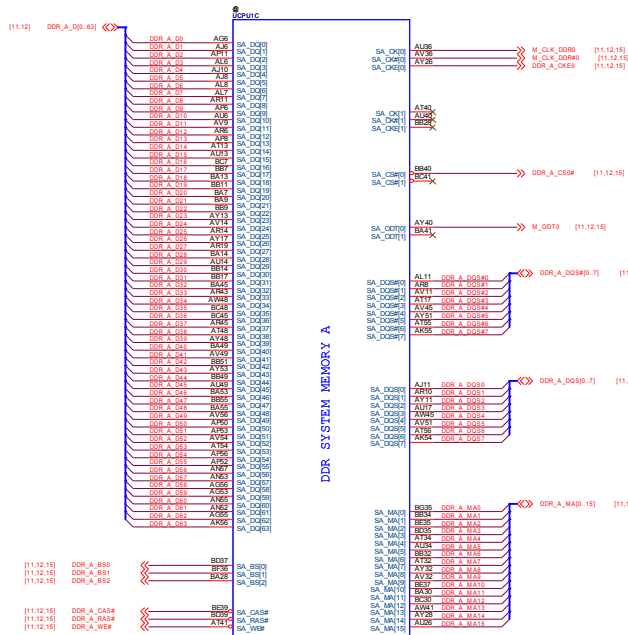


## PM, XDP, CLK, S3 Reduce, PLTRST

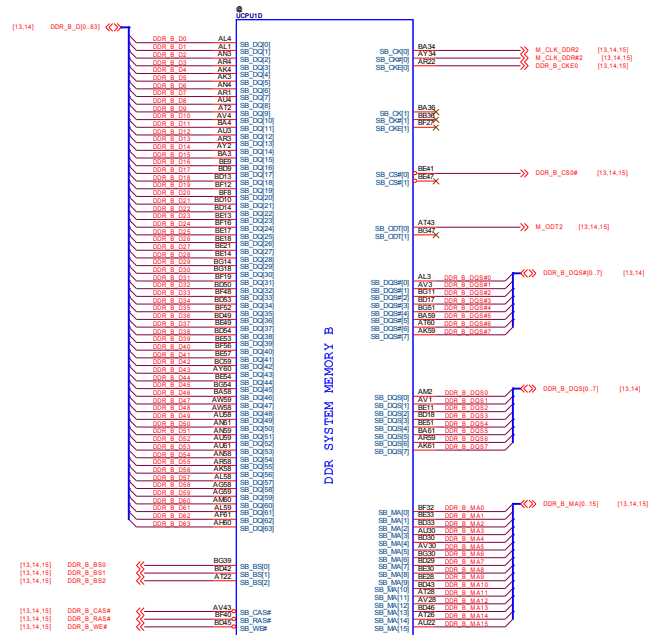


DDR structure 1R X 8

DDR structure 1R X 8

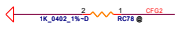
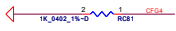
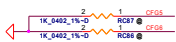
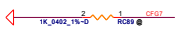


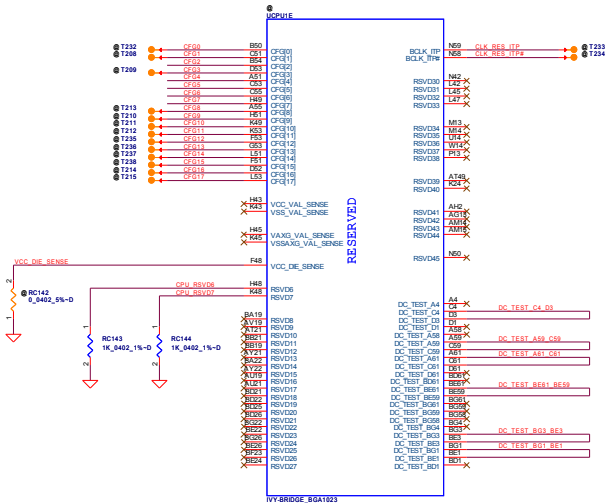
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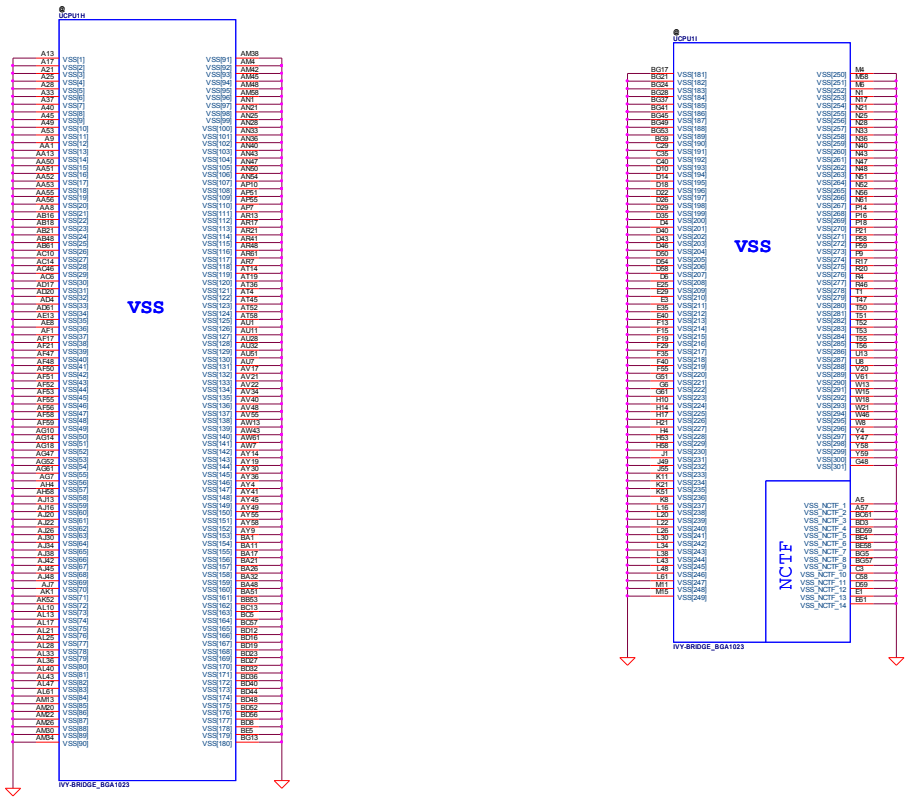
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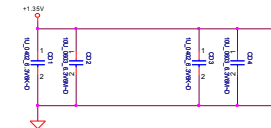
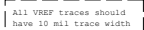
# CFG Straps for Processor

	
<b>PEG Static Lane Reversal - CF92 is for the 16x</b>	
CFG2	1: (Default) Normal Operation; Lane # definition matches socket pin map definition 0: Lane Reversed
	
<b>Display Port Presence Strap</b>	
CFG4	1: Disabled; No Physical Display Port attached to Embedded Display Port 0: Enabled; An external Display Port device is connected to the Embedded Display Port
	
<b>PCIE Port Bifurcation Straps</b>	
CFG[6:5]	11: (Default) x16 - Device 1 functions 1 and 2 disabled 10: x8, x8 - Device 1 function 1 enabled ; function 2 disabled 01: Reserved - (Device 1 function 1 disabled ; function 2 enabled) 00: x8, x4, x4 - Device 1 functions 1 and 2 enabled
	
<b>PEG DEFER TRAINING</b>	
CFG7	1: (Default) PEG Train immediately following xMRESets de assertion 0: PEG Wait for BIOS for training







+3VS  **UP17** **Non-CIS par**



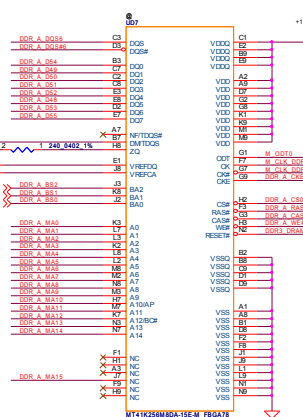
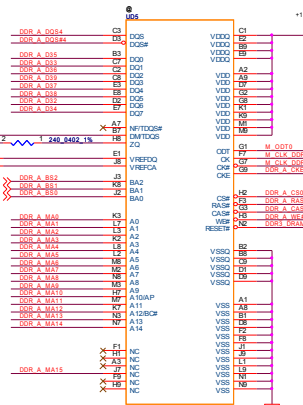
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[11.15.7] DOR\_A\_DQ[9:7] <>  
[11.15.7] DOR\_A\_DQ[4:3] <>  
[11.15.7] DOR\_A\_MAP[15]

All VREF traces should  
have 10 mil trace width



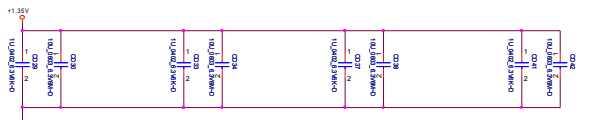
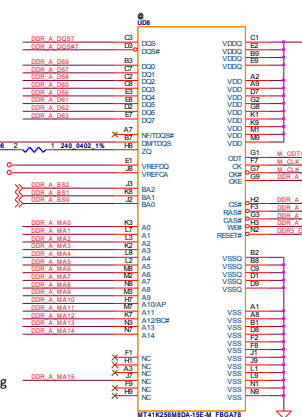
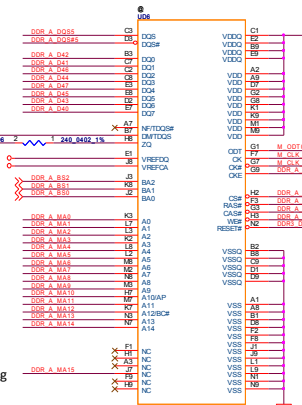
For 4Gb Using

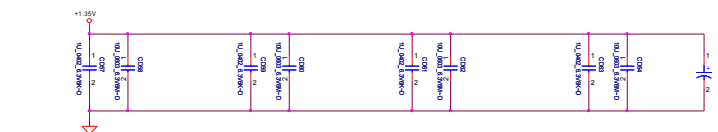
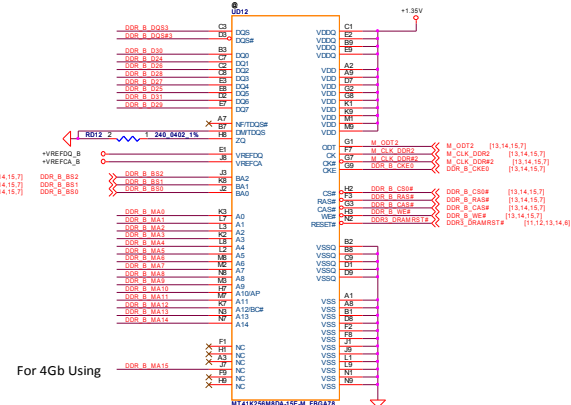
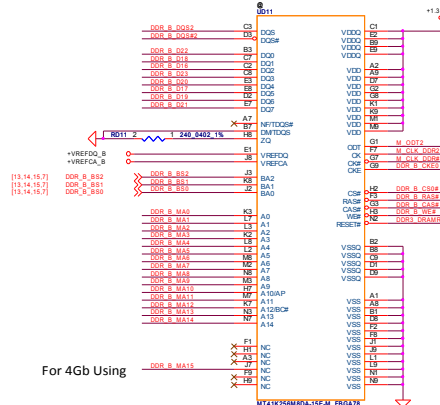
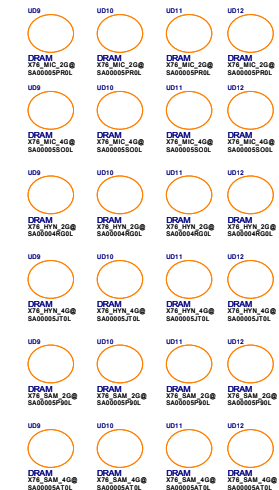
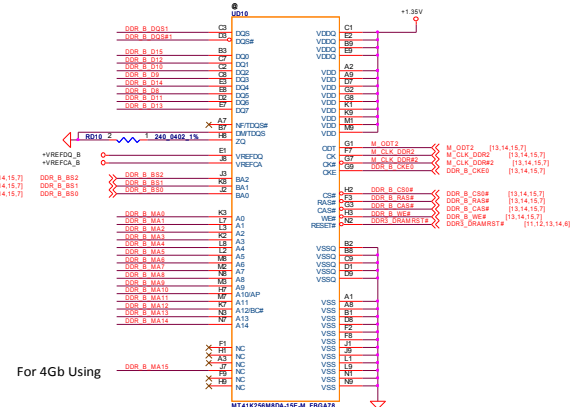
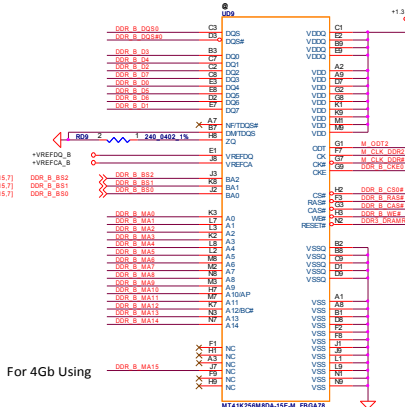
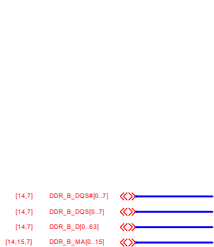
For 4Gb Using



For 4Gb Using

For 4Gb Using





## Memory Channel B SPD EEPROM

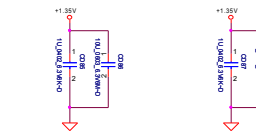
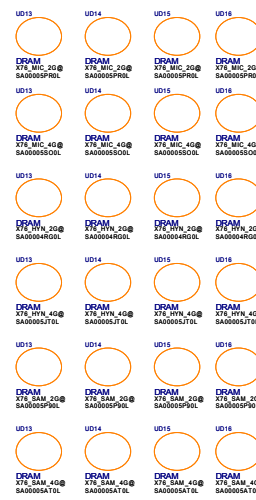


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Title		P13-DDRIII Channel B Lower	
Rev		1.0	
Date		Friday, September 28, 2012	
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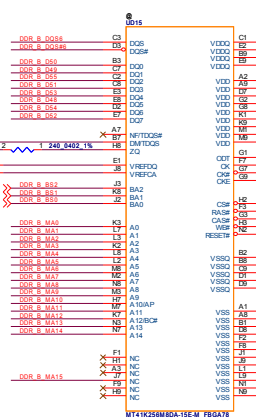
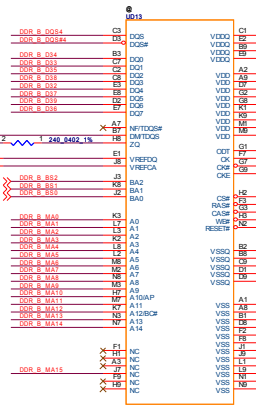
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[13.7] DOR\_B\_DQ9[4:3] X  
[13.15.7] DOR\_B\_MAP[15]

All VREF traces should have 10 mil trace width



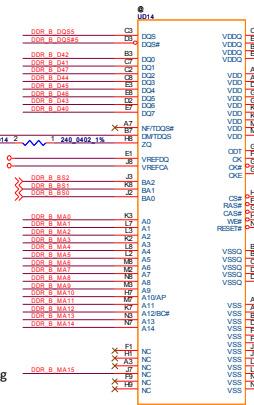
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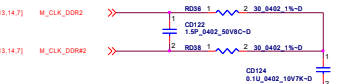
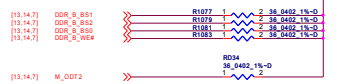
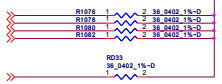
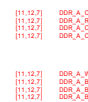
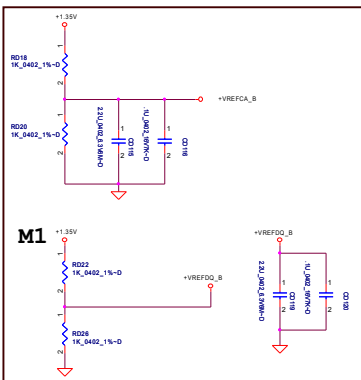
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For 4Gb Using

For 4Gb Using





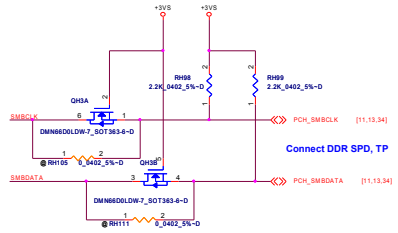
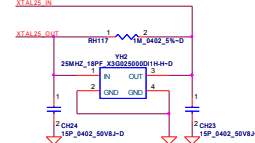
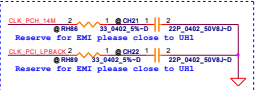
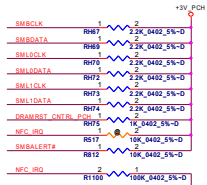
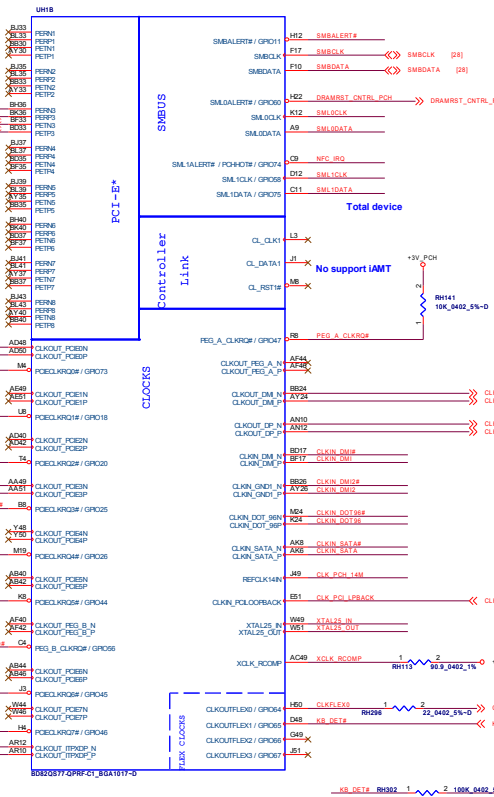


MiniWLAN-->

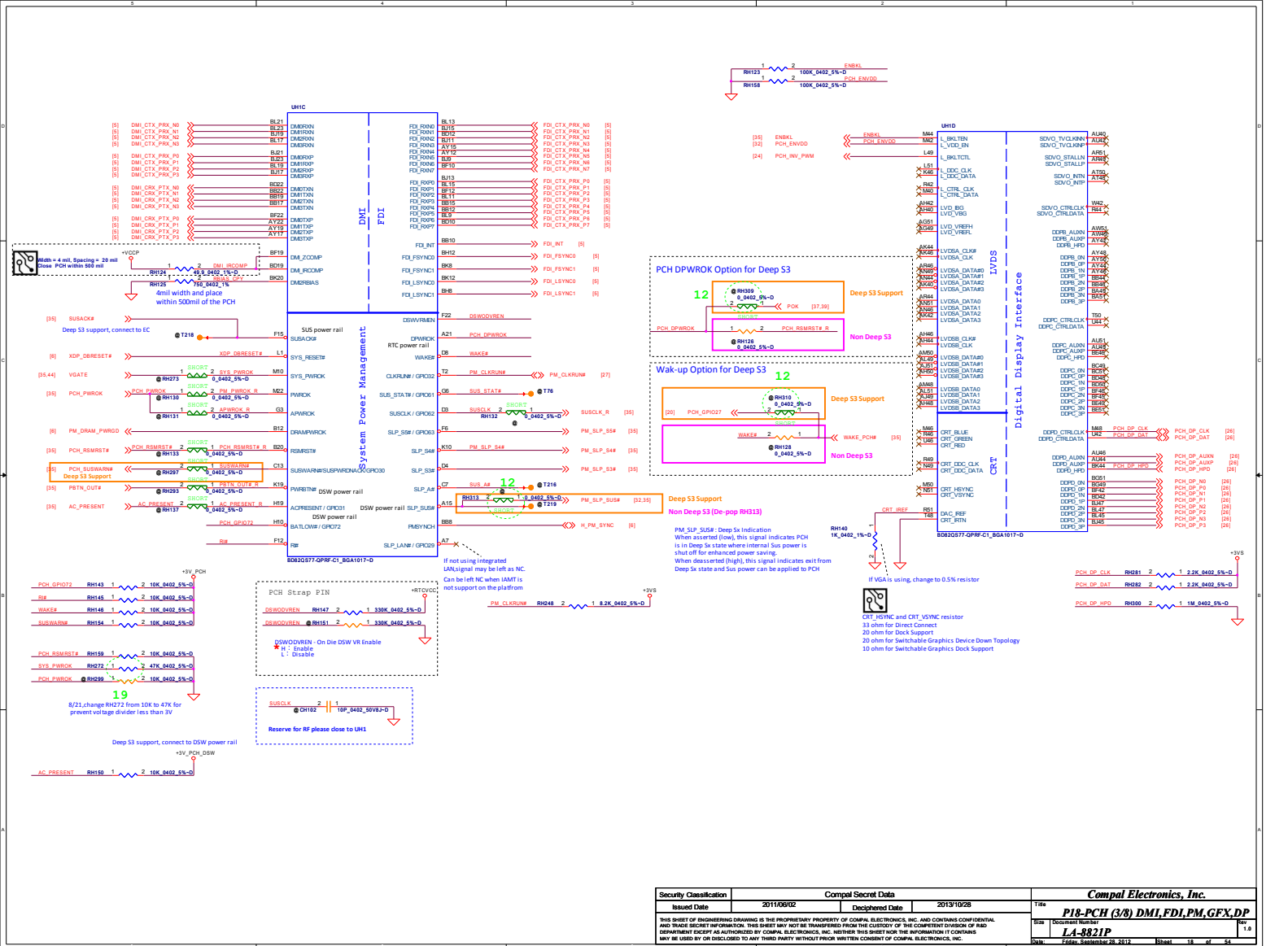
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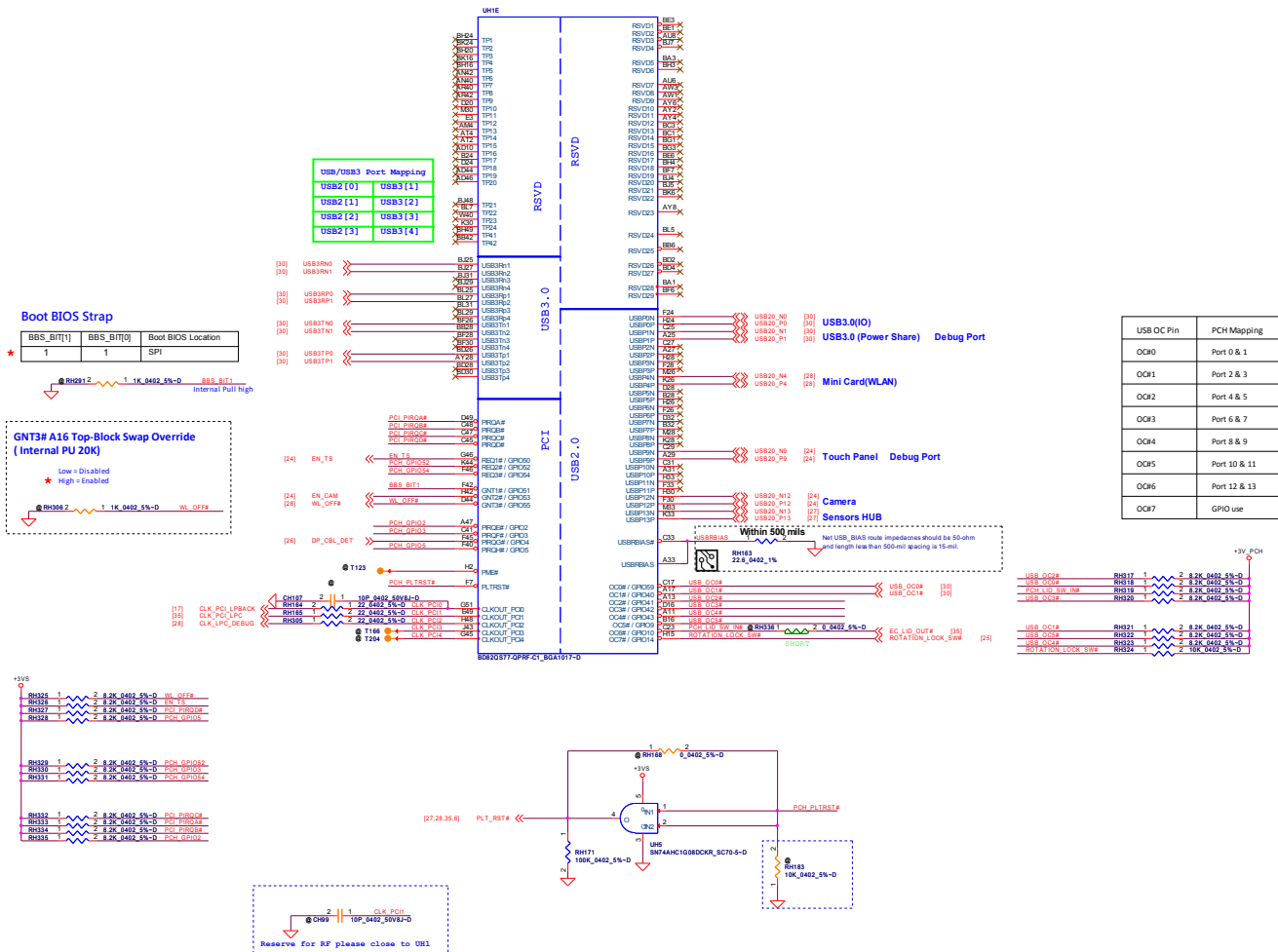
MiniWLAN-->

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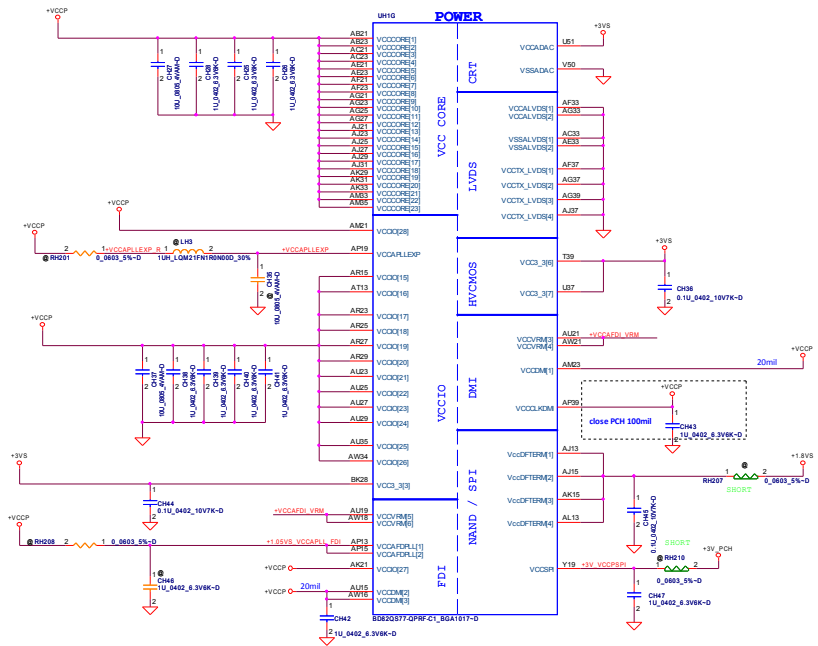


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LA-8821P			Rev	1.0
Date: September 18, 2012			Sheet	17 of 54



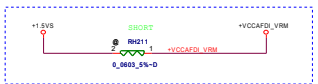






PCH Power Rail Table		
Voltage Rail	Voltage	80 Tcomax Current (A)
V_PROC_IO	1.05	0.001
V5REF	5	0.001
V5REF_Sua	5	0.001
Vcc3_3	3.3	0.266
VccADAC	3.3	0.001
VccADPLL	1.05	0.08
VccADPLL	1.05	0.08
VccCore	1.05	1.3
VccDMI	1.05	0.042
VccIO	1.05	2.925
VccSW	1.05	1.01
VccSPI	3.3	0.02
VccDSW	3.3	0.003
VccSMD	1.8	0.19
VccRTC	3.3	6 uA
VccSua3_3	3.3	0.119
VccSuaRDA	3.3 / 1.5	0.01
VccVMM	1.8 / 1.5	0.16
VccL2DMI	1.05	0.02
VccSSC	1.05	0.095
VccDIPTCLK	1.05	0.055
VccLVDS	3.3	0.001
VccTX_LVDS	1.8	0.06

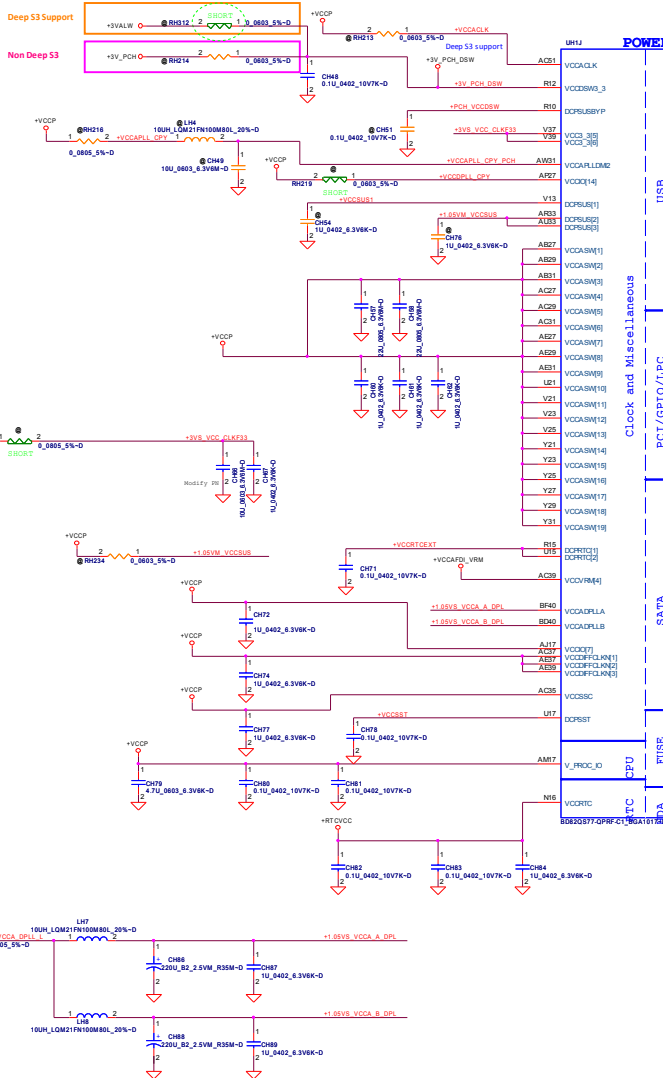
VCCVMM = 160mA detail waiting for newest spec



13

Deep S3 Support

Non Deep S3



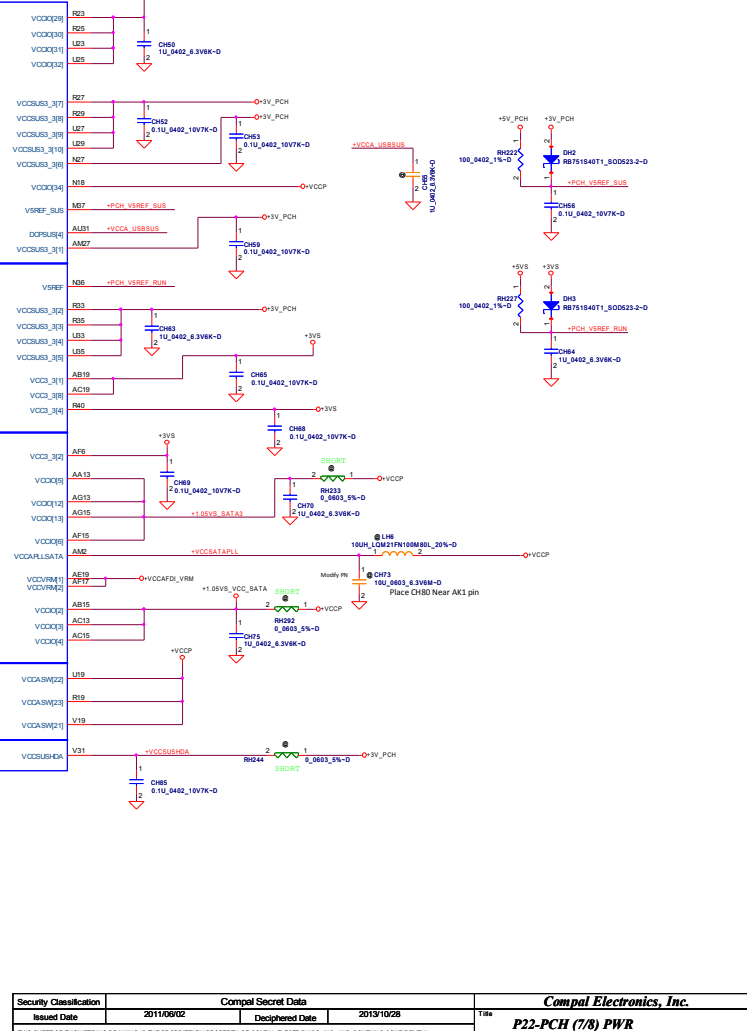
VCC3\_3 = 266mA detail waiting for newest spec  
VCCM1 = 42mA detail waiting for newest spec

POWER

USB  
PCI/GPIO/LPC  
SATA  
FUSE  
CPU  
I/O

Deep S3 Support

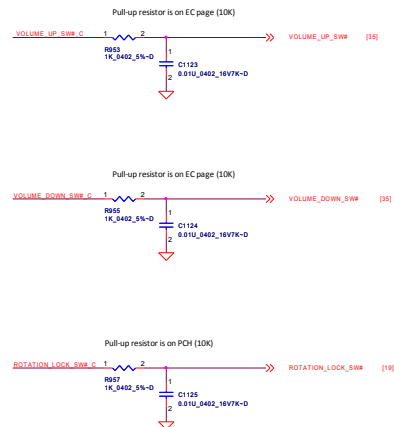
Non Deep S3



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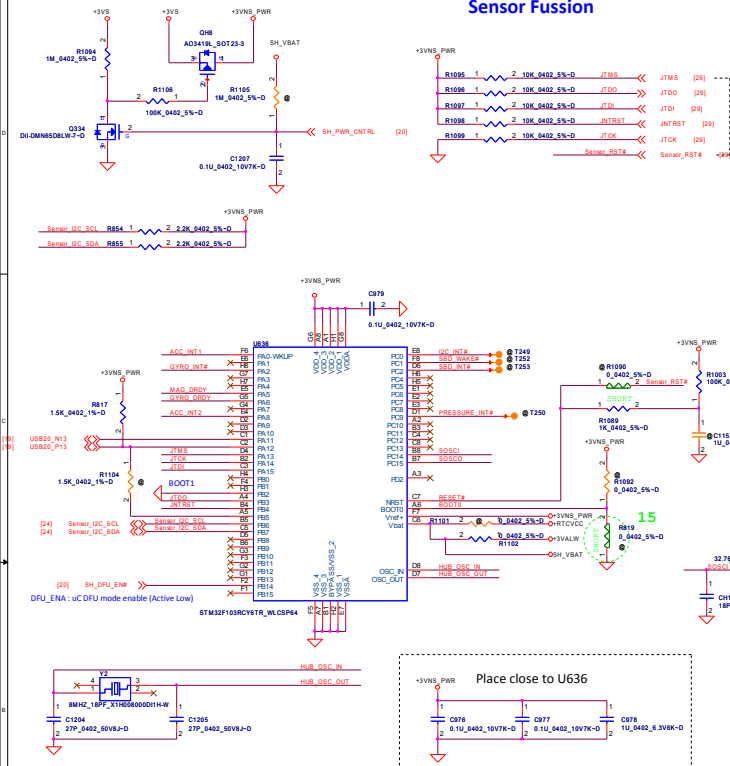




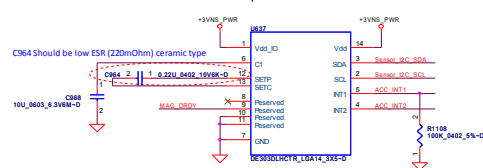




## Sensor Fussion



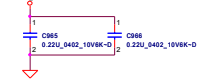
## e-Compass + Accelerometer



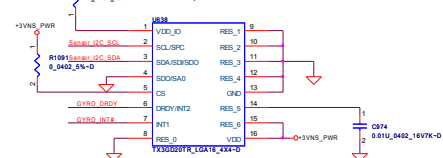
C964 Should be low ESR (220mOhm) ceramic type

Connect to mSATA card  
Debug/Programming used

**PWR** Place close to U637 Pin1, 14

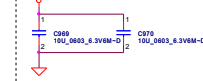


## Gyro

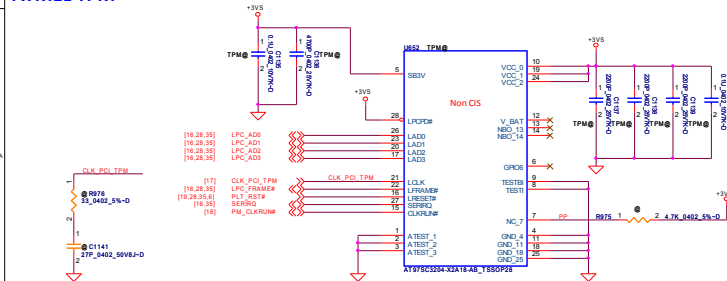


8/20, Follow DFB suggest, modify Y1 footprint

Place close to U638 Pin 1,15,16

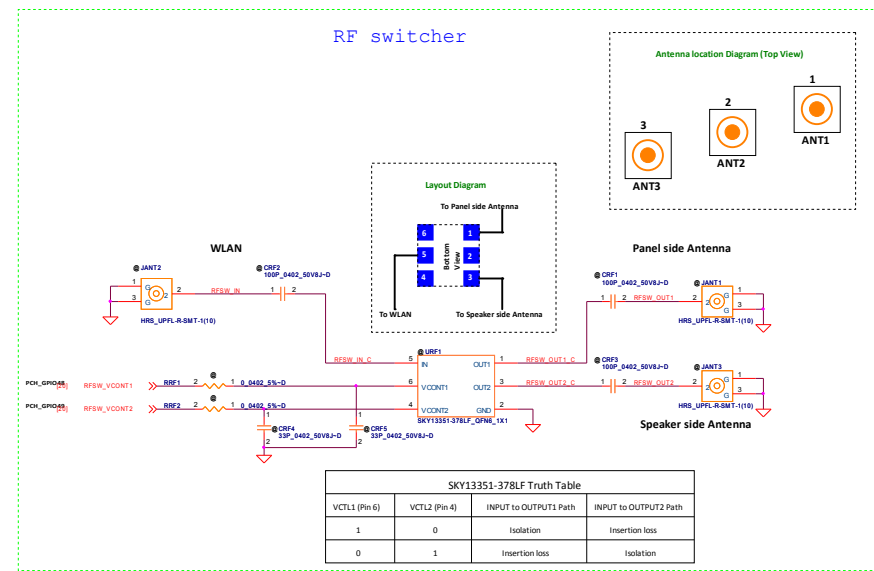
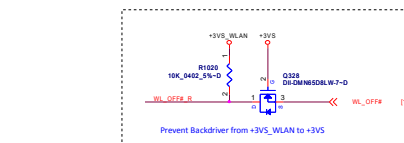
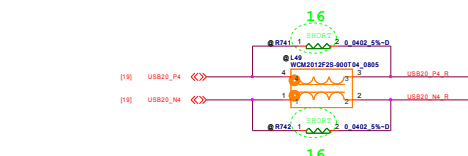
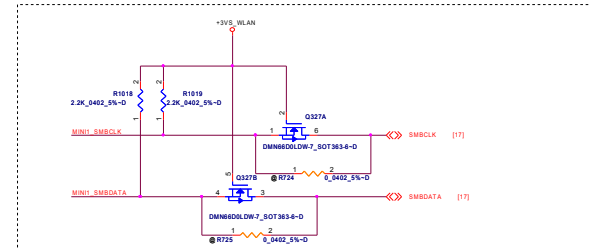
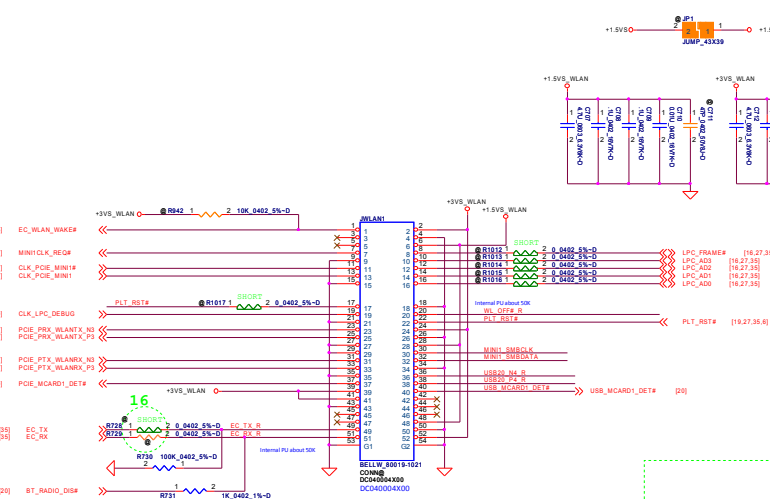


## ATMEL TPM



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			File Description	1.0
			File Name	LA-8821P
			Date	2012.06.02
			Sheet	27 of 34

# Wireless LAN

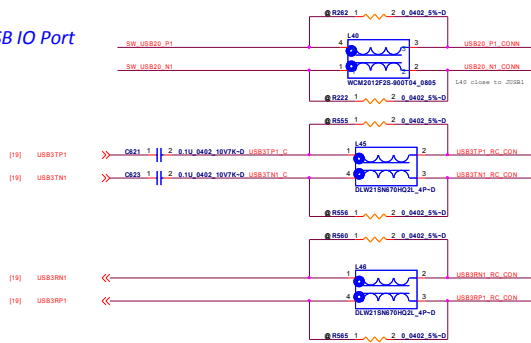


SKY13351-378LF Truth Table			
VCTL1 (Pin 6)	VCTL2 (Pin 4)	INPUT to OUTPUT1 Path	INPUT to OUTPUT2 Path
1	0	Isolation	Insertion loss
0	1	Insertion loss	Isolation

ME Decide using 16 pin conn  
MB 16 <-----> 15 pin NFC (Reserved Connection)

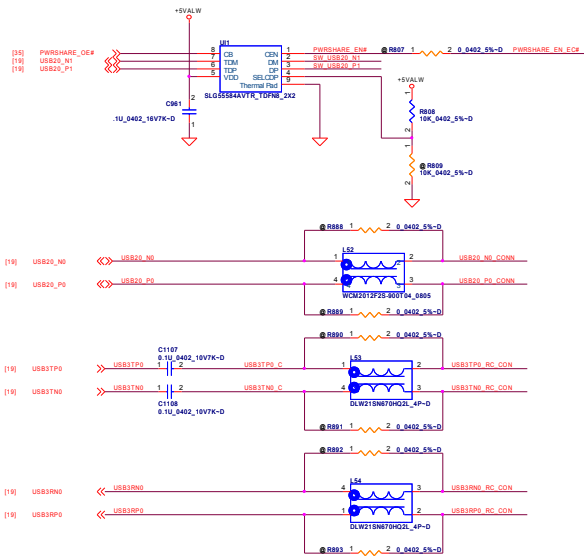


## USB IO Port



## Power share

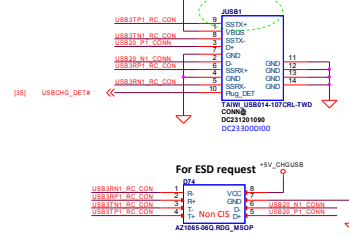
CB	Function
L	auto detection charger identification active
II	DP/DNM-TDP/TDM



Modify JUSB1 connector mfr. P/N from USB014-107CRL-TW to USB014-107CRL-TWD (remove mayla only)

38

## USB 3.0 CONN

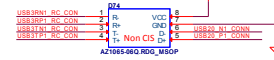


close to JUSB1

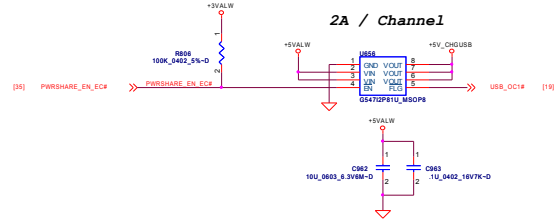
2.0A



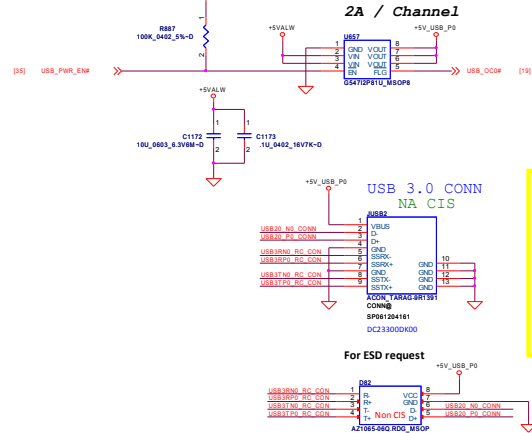
For ESD request



## 2A / Channel



## 2A / Channel



close to JUSB2

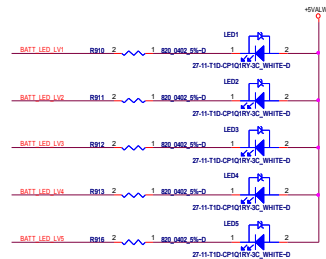
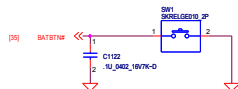
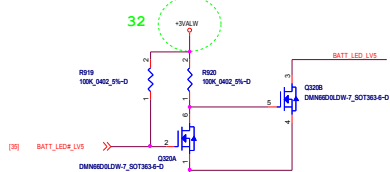
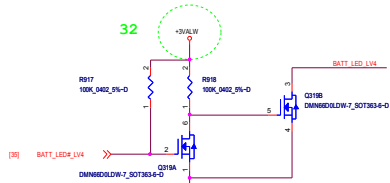
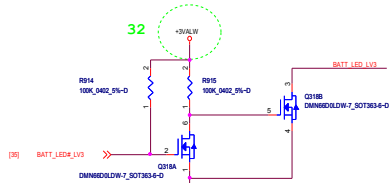
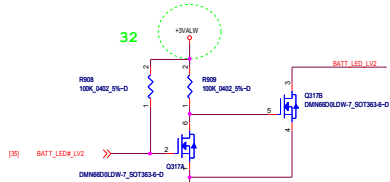
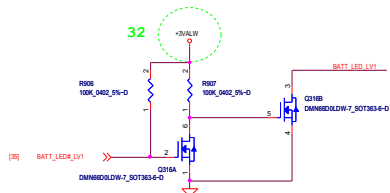
2.0A



For ESD request



Security Classification			Compal Secret Data		2013/10/28		Compal Electronics, Inc.	
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							P30-USB 3.0 IO CONN	
							Rev. 1.0	
							Date: September 2013	
							Page 10 of 54	

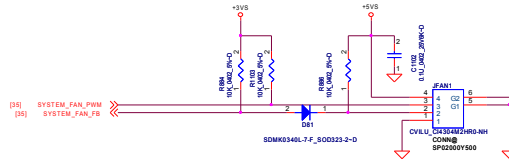


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				LA-8821P	
				Rev	
				1.0	
				Date	
				Eating September 28, 2012	
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				31 of 34	

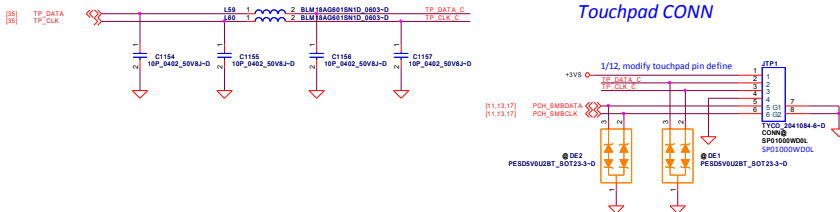




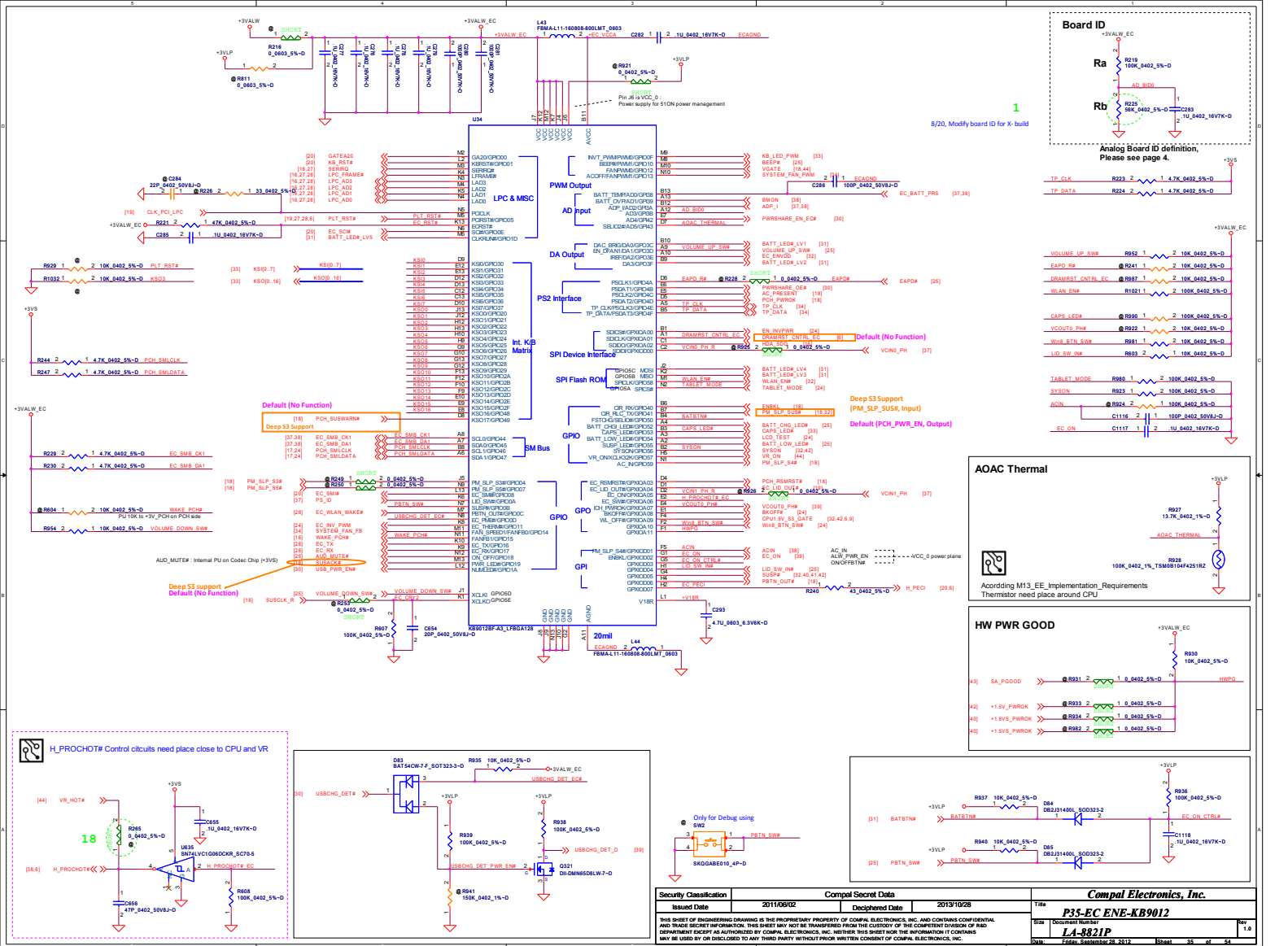
## FAN CONN

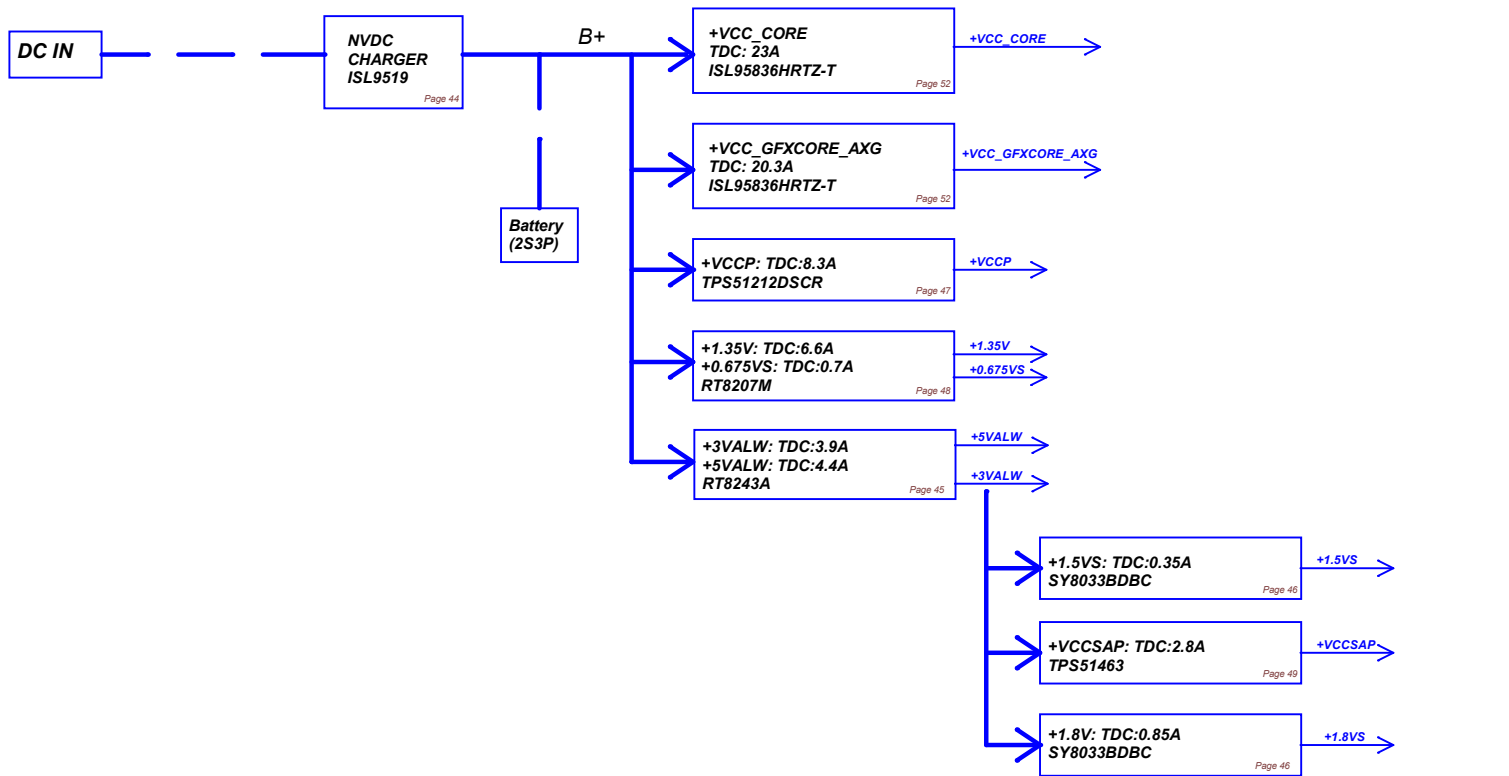


## Touchpad CONN



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				Date	Final: September 28, 2012
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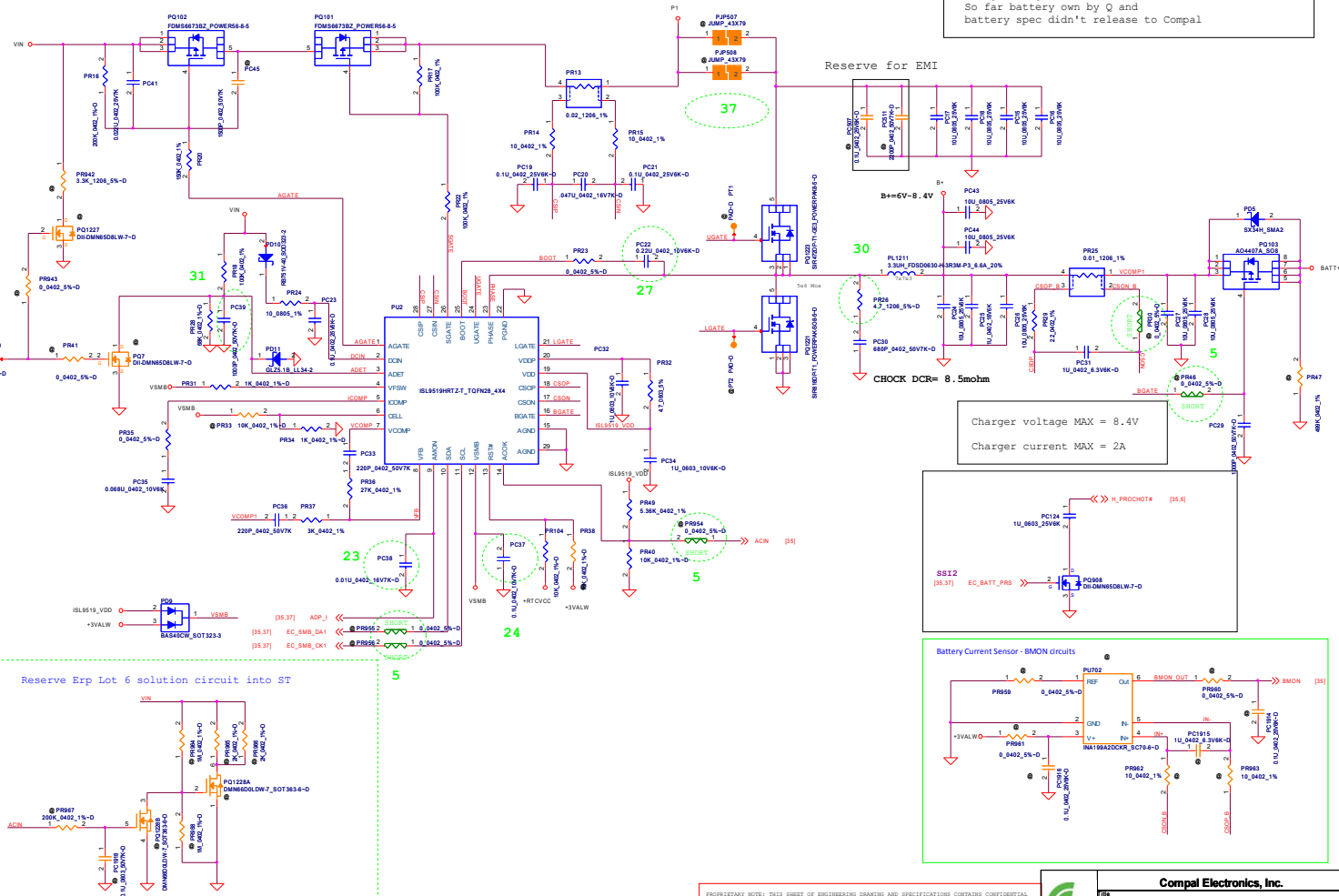




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(battery = 2S3P -->  
 2150mAh\*3= 6450mAh  
 ---->6450mAh\*0.6C=3.9A)  
 ---->6450mAh\*0.9C=5.8A)  
 Design charger current around 6A for worst case  
 So far battery own by Q and  
 battery spec didn't release to Compal



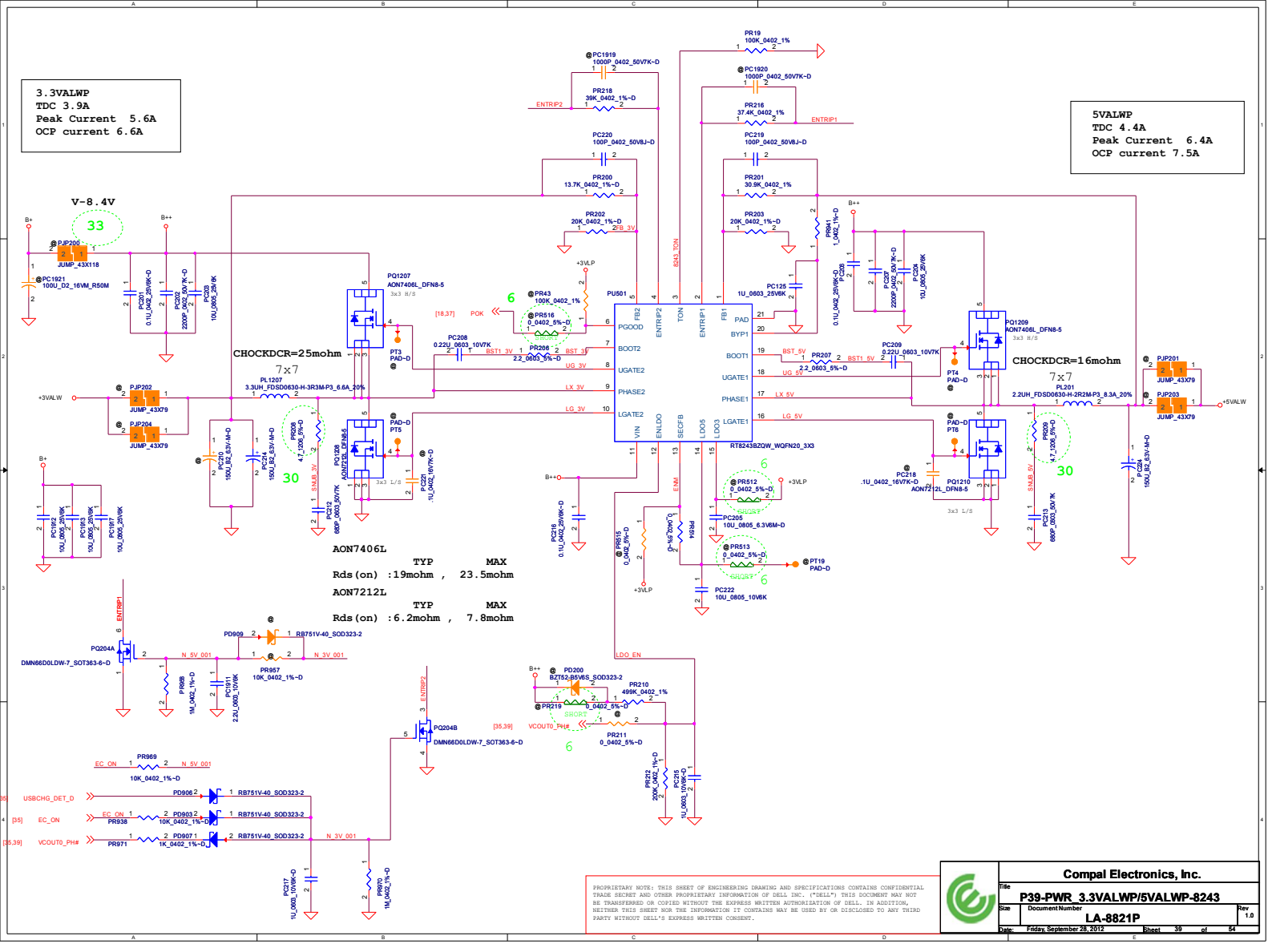
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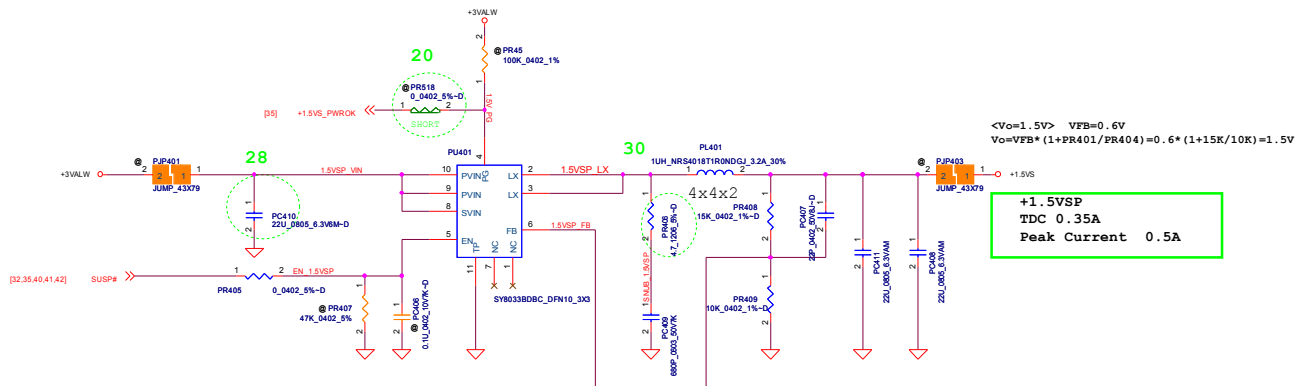
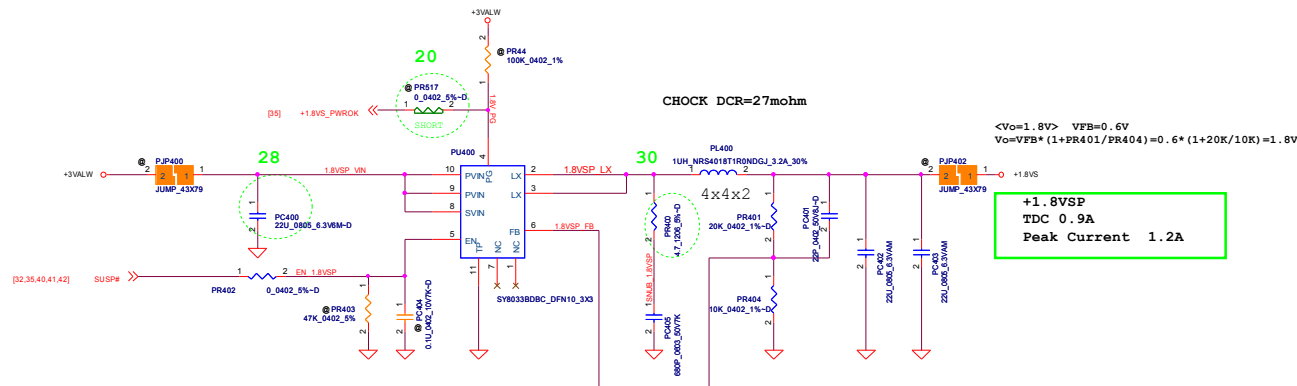
```

3.3VALWP
TDC 3.9A
Peak Current 5.6A
OCP current 6.6A

```

```
5VALWP
TDC 4.4A
Peak Current 6.4A
OCP current 7.5A
```



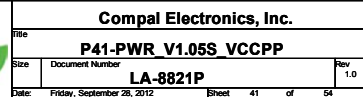
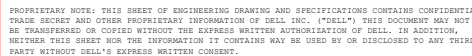


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File	P40-PWR_1.8VSP/1.5VSP		
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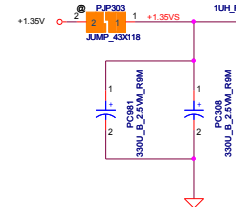
Rev 1.0



B+=6V-8.4V

35

CHOCK DCR=16mohm



1.35VP  
TDC 6.6A  
Peak Current 9.4A  
OCF current 11.2A

AON7406L  
TYP MAX  
Rds(on) : 19mohm , 23.5mohm  
AON7212L  
TYP MAX  
Rds(on) : 6.2mohm , 7.8mohm

21

0.675Volt +/- 5%  
TDC 0.7A  
Peak Current 0.9A  
OCF Current 1.2A

22

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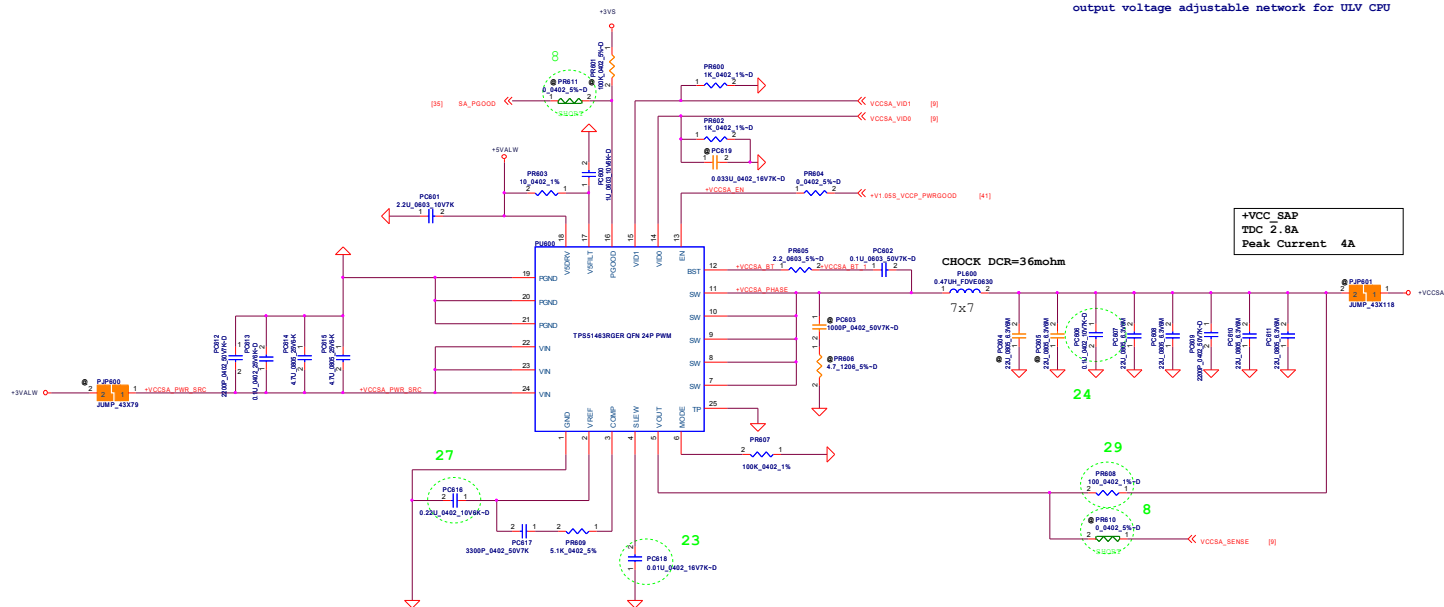
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Title	P42-PWR +1.35VP/0.675VSP		
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12/15 update value

VID [0]	VID[1]	VCCSA Vout
0	0	0.9V
0	1	0.85V
1	0	0.775V
1	1	0.75V

output voltage adjustable network for ULV CPU

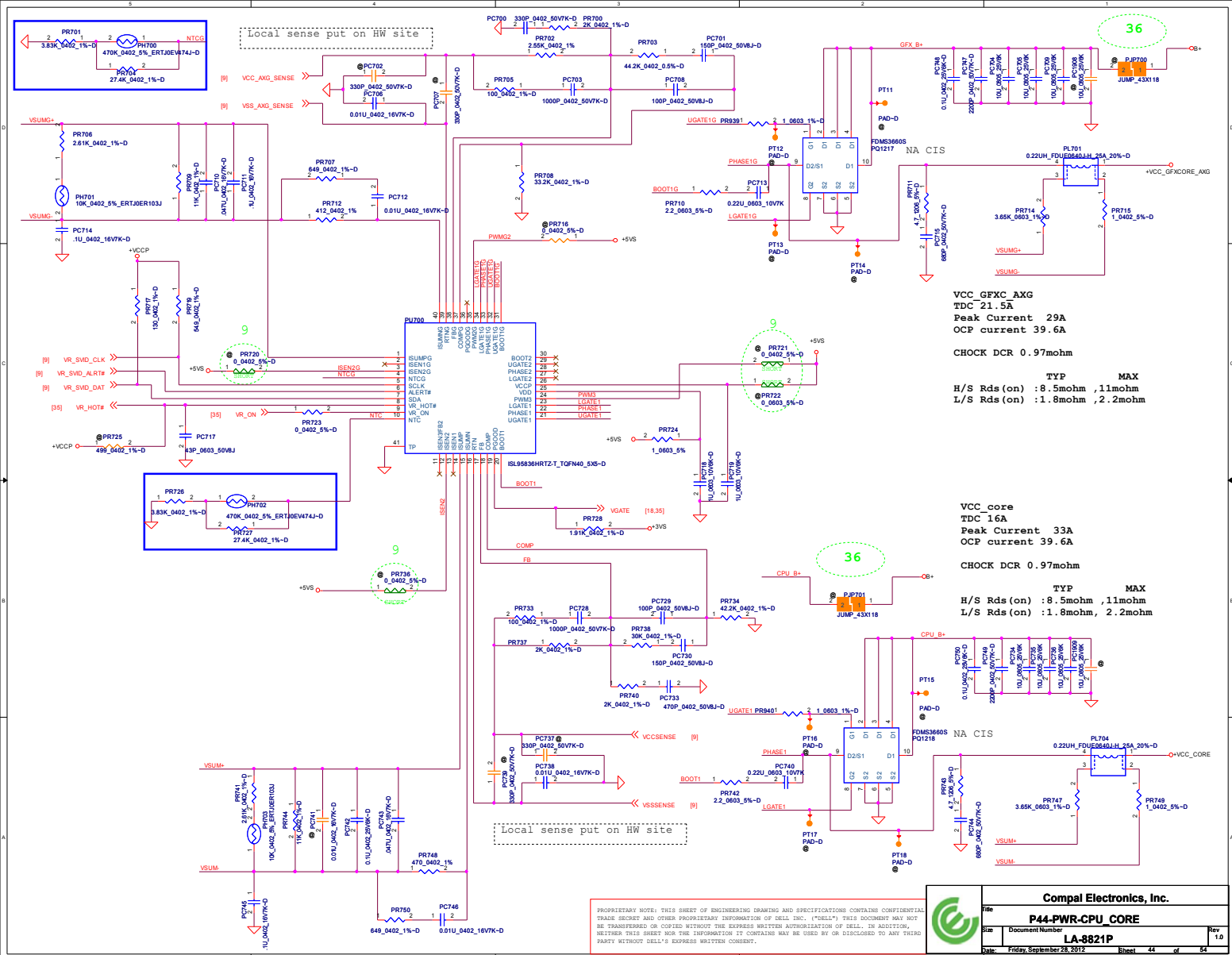
The 1k PD on the VCCSA VIDs are empty.  
These should be stuffed to ensure that  
VCCSA VID is 00 prior to VCCIO stability.



+VCC SAP  
TDC 2.8A  
Peak Current 4A

CHOCK DCR=36mohm

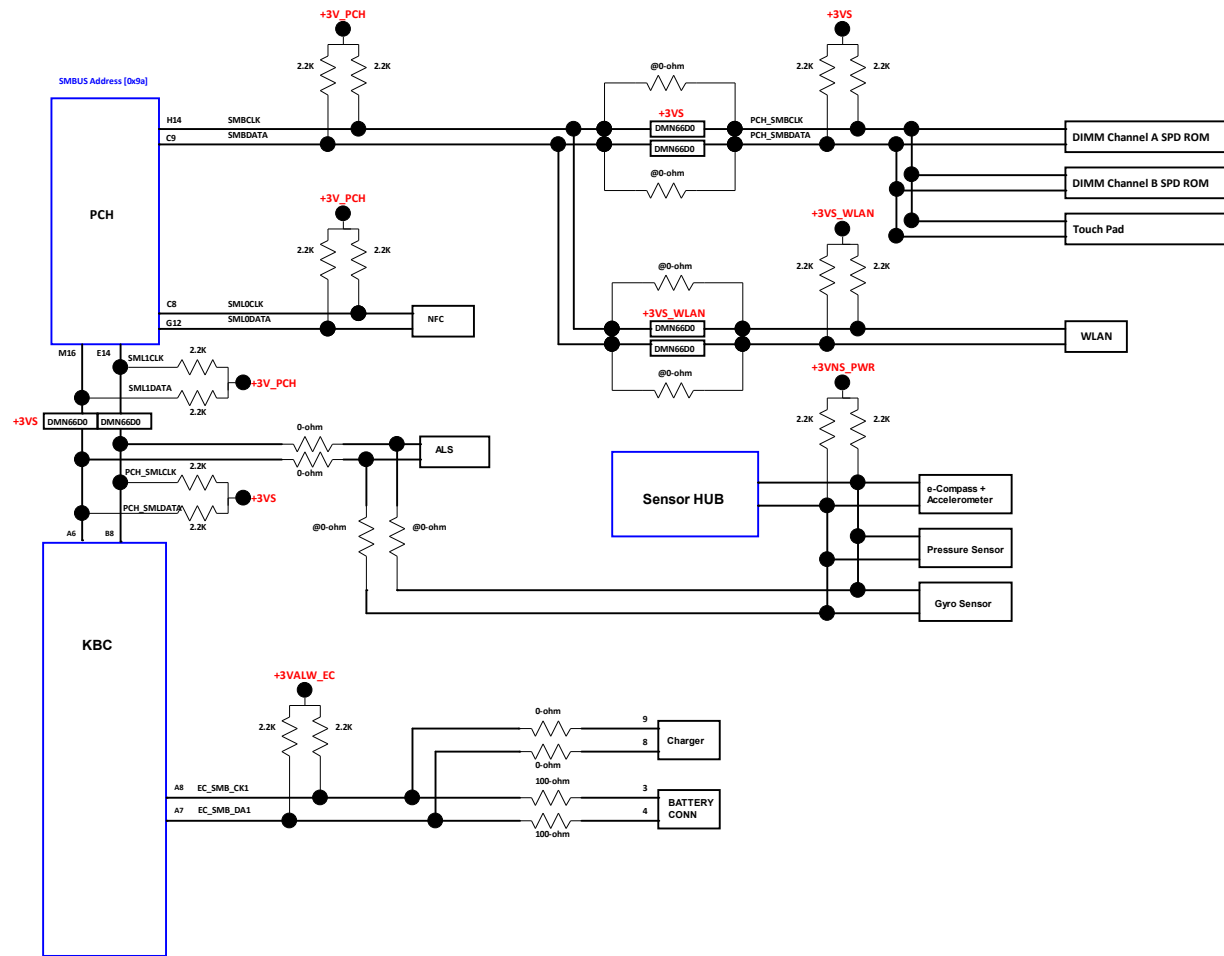
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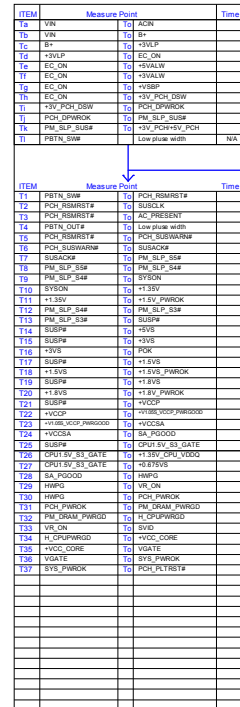
File	P44-PWR-CPU_CORE		
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## Discrete Power On Sequence

[Battery only, AC absent]



# Version Change List (P. I. R. List)

# Page 1

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	24	eDP/ Camera CONN	2012-03-02	Compal_Vicent	eDP touch sreen's power missing in BBU stage	R1084 BOM structure is "0" (de-pop), change to POP	X01
2	35	EC ENE-KB9012	2012-03-05	Compal_Vicent	Debug power switch un-work, short to GND	SW2 OrCard symbol is different with specification Correct SW2 symbol	X01
3	35	EC ENE-KB9012	2012-03-05	Compal_Vicent	Insert USB device into power share port, the 3V/5V can't power-on automatic in S5/DC mode	R922 need de-pop to avoid become voltage divider with R938 and PD906	X01
4	35	EC ENE-KB9012	2012-03-05	Compal_Vicent	WLAN power will be turn-on a short time while adapter plug in	WLAN_EN# signal PU resistor R1012 need pop to prevent Hi-Z state while EC during initial state	X01
5	27	Sensor Fussion / TPM	2012-03-06	Compal_Vicent	Wrong power rail on Gyro sensor VDD_I0 pin	Correct Gyro sensor U638 VDD_I0 power from +3VS to +3VNS_PWR	X01
6	27	Sensor Fussion / TPM	2012-03-07	Compal_Vicent	Follow Intel Sensor HUB HWDG v0.5 to modify design	1. Sensor HUB uC (U636) VBAT power change from +RTCVCC to +3VALW power 2. Sensor HUB load switch power rail change from +3VALW to +3VS	X01
7	06	CPU(2/6) PM,XDP,CLK,S3,PLT	2012-03-09	Compal_Vicent	Change design to support Deep S3	1. De-pop RC72, Pop RC145 and R1035, DRAM_RST# gated by EC 2. Pop RH313, PCH Suspend power rail control by PCH 3. Pop RH310, De-pop RH128, Wake-up event change connect to PCH GPIO27 4. Pop RH309, De-pop RH126, PCH DPWROK change to +3VALW PG 5. Pop RH312, De-pop RH214, PCH VCCDSW change to +3VALW 6. R225 value change to 8.2K, Change Board ID to 1 for identify Deep S3 suport PCBA	X01
	18	PCH (3/8) DML,FDP,CLK,DP					
	22 35	PCH (7/8) PWR EC ENE-KB9012					
8	27	Sensor Fussion / TPM	2012-03-12	Compal_Vicent	Change e-Compass, Gyro, Pressure sensor to DELL P/N	1. U637 P/N change from SA00004M00 to SA00004M0L 2. U638 P/N change from SA00005HQ00 to SA00005HQ0L 3. U653 P/N change from SA00004TTD0 to SA00004TTDL	X01
9	27 17	Sensor Fussion / TPM PCH (2/8) PCIE, SMBUS, CLK	2012-03-15	Compal_Vicent	1. Follow Vendor EA result, change 8MHz crystal Capacitor value 2. Follow Vendor EA result, change 25MHz crystal Capacitor value	1. C1204 and C1204 value change from 18pF to 27pF 2. CH23 and CH24 value change from 15pF to 12pF	X01
10	24	eDP/ Camera CONN	2012-03-15	Compal_Vicent	Win8 Button doesn't work, Double PU in P24 and P35 on net Win8_BTN_SW#	Page24 R977 de-pop, R978 change from 10K to 1K	X01
11	21	PCH (6/8) PWR	2012-03-20	Compal Procurement	Change all TAIYO bead to MURATA	P21, LH3	X01
	22	PCH (7/8) PWR				P22, LH4, LH6, LH7, LH8	
	25	IOL Conn				P25, LH9	
12	27 29	Sensor Fussion / TPM mSATA / NFC Conn	2012-03-21	Compal_Vicent	Sensor HUB JDG1 is interference to ME design	Connect U636 JTAG interface to mSATA mini-card JSATA1 Pop R1090 0-ohm	X01
13	20 27	PCH (5/8) GPIO, CPU, MISC Sensor Fussion / TPM	2012-03-22	Intel & Compal_Vicent	Follow Intel Sensor HUB design DG0.5, remove SBD_INT# connection to PCH	Remove SBD_INT# connection to Sensor HUB uC and rename to PCH_GPIO15 Add Test pin on SBD_INT# net	X01
14	19 20	PCH (4/8) PCL USB, NVDRAM PCH (5/8) GPIO, CPU, MISC	2012-03-22	Compal_Mandy	Rotation lock can't detect by event trigger method	Rotation Lock signal change connect from PCH GPIO48 to GPIO14	X01
15	17 19	PCH (2/8) PCIE, SMBUS, CLK PCH (4/8) PCL USB, NVDRAM	2012-03-23	Compal_Mandy	Intel D53 known issue, if GPIO11 drive low in D53 then re-inserted AC the system will wake-up all way.	Follow BIOS team suggestion, change EC_LID_OUT# connection from GPIO11 to GPIO10	X01
16	5	CPU(1/6) DML,FDP,PEG	2012-03-28	Compal_Jay	Update CPU to L-1 P/N	Update CPU to L-1 P/N((I5-3317U/I5-3427U/I7-3517U/I7-3667U)	X01
17	17 29	PCH (2/8) PCIE, SMBUS, CLK mSATA / NFC Conn	2012-03-28	Compal_Jay	Follow Intel NFC review result	Page17 R517 de-pop. Page29 1. add R1100 100K PD, 2. de-pop R973, 3. Pop R974 and change from 10K to 0 ohm.	X01
18	20 27	PCH (5/8) GPIO, CPU, MISC Sensor Fussion / TPM	2012-04-02	Compal_Jay	Add TPM BOM Optional (PCH_GPIO16), PU=WTPM/PD=W/O TPM	TPM@=support TPM, NTPM@=without TPM	X01
19	18 35	PCH (3/8) DML,FDP,CLK,GFX,DP EC ENE-KB9012	2012-04-02	Compal_Jay	For meet ErP Lot 6, remove PM_SLP_S4# (PCH side) connection to EC.	1.Remove PM_SLP_S4# connection to EC and add test pin. 2.Rename POK to EC_DPWROK. Rename PM_SLP_S4# to EC_DPWROK.	X01
20	17 29	PCH (2/8) PCIE, SMBUS, CLK mSATA / NFC Conn	2012-04-03	Compal_Jay	Modify net name from NFC_IRQ# to NFC_IRQ.	Modify net name from NFC_IRQ# to NFC_IRQ.	X01

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## Version Change List (P. I. R. List)

## Page 2

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
21	38	PWR_Charger(SL9519)	2012-04-05	Power_Jeff	Add 0 ohm for EC_SMB_DA1 and EC_SMB_CK1 for charger test.	Add 0 ohm for EC_SMB_DA1 and EC_SMB_CK1 for charge test.	X01
22	44	PWR-CPU_CORE	2012-04-05	Power_Jeff	Follow intersil EA test result, modify PR737 form 1.91K to 2.0K for CPU Load Line.	Modify PR737 form 1.91K to 2.0K for CPU LL	X01
23	44	PWR-CPU_CORE	2012-04-05	Power_Jeff	Modify GFXC_core and CPU_core TDC and OCP current note	VCC_GFXC_AXG TDC from 20.3A -->21.5A OCP current from 34.5A to 39.6A VCC_Core TDC from 23A -->16A OCP current from 39A to 39.6A	X01
24	33	SCREWH/KB/RTC	2012-04-09	Compal_Jay	Follow ME dxf file update	Delete H15 and add H21 EMI spring	X01
25	18	PCH (3/8) DMLFDLPM/GFX,DP EC ENE-KB9012	2012-04-09	Compal_Jay	Follow EC suggest modify back PM_SLP_S4# connection to EC.	1. Follow EC suggest modify back PM_SLP_S4# connection to EC. 2.Modify EC_DPWROK back to POK Modify C_DPWROK back to PM_SLP_S4#.	X01
26	27	Sensor Fussion / TPM	2012-04-09	Compal_Jay	Follow TXC crystal EA report	Follow TXC EA report modify CH1202/CH1203 from 6.8PF to 18PF	X01
27	16	PCH (1/8) SATA,HDA,SPL LPC	2012-04-09	Compal_Jay	Follow TXC crystal EA report	Follow TXC EA report modify CH2/CH3 from 18PF to 22PF	X01
28	35	EC ENE-KB9012	2012-04-09	Compal_Jay	Modify board ID to Revision :X01	Modify R225 from 8.2K to 18K	X01
29	38	PWR_Charger(SL9519)	2012-04-09	Power_Jeff	Follow Charger EA, modify switching frequency to slow	Change PL1211 form 1uH to 3.3uH	X01
30	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify CPU OCP Value.	change PR748 from 422 to 442 ohm	X01
31	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify value for CPU compensator.	Change PC729 from 47p to 100pF	X01
32	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify value for CPU compensator.	Change PR738 from 267K to 220K ohm	X01
33	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify GFX OCP value.	change PR712 from 360 to 392 ohm	X01
34	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify PR737 form 1.91K to 2.0K for GFX Load Line.	Change PR702 from 2.26K to 2.55K ohm	X01
35	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify value for GFX compensator.	Change PC708 from 47p to 100pF	X01
36	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil EA test result, modify value for GFX compensator.	Change PR703 from 267K to 220K ohm	X01
37	44	PWR-CPU_CORE	2012-04-09	Power_Jeff	Follow intersil suggest, change input caps from 4.7uF to 10uF.	Change PC704,PC705,PC709,PC734,PC735,PC736 form 4.7uF to 10uF Add PC1908, PC1909 to 10uF de-pop	X01
38	39	PWR_3_3VALWP/SVALWP-8243	2012-04-09	Power_Jeff	Modify SECFB connection to LDO3 (DEM)	Change PR514 form 0ohm to NC Change PR515 form NC to 0ohm	X01
39	39	PWR_3_3VALWP/SVALWP-8243	2012-04-09	Power_Jeff	For 3/5V can't turn-off in S5 state while system change form AC to DC mode	Change PC217 form 2.2uf to NC	X01
40	42	PWR_3_3VALWP/SVALWP-8243	2012-04-09	Power_Jeff	Avoid +1.35V output noise affect FB sensor result, modify net name from +1.35V to +1.35VS	Modify net name from +1.35V to +1.35VS	X01
41	11	DDRIII Channel_A Lower	2012-04-10	Compal_Jay	Modify DDR3L P/N for PT build	MICRON 2Gb/1600/42nm :SA00005PROL	X01
	12	DDRIII Channel_A Upper				MICRON 4Gb/1600/30nm :SA00005SOOL	
	13	DDRIII Channel_B Lower				HYNIX 2Gb/1600/38nm :SA00004RGOL	
	14	DDRIII Channel_B Upper				HYNIX 4Gb/1600/38nm :SA00005J7OL SAMSUNG 2Gb/1600/35nm :SA00005P9OL SAMSUNG 4Gb/1600/35nm :SA00005ATOL	
42	16~23	PCH (1/8) SATA,HDA,SPL LPC	2012-04-10	Compal_Jay	Modify PCH P/N for PT build	SA00005L31L :S IC BD82Q577 SLI88 C1 8GA 1017 PCH	X01
43	42	PWR_+1.35VP/0.675VSP	2012-04-10	Power_Jeff	Delay +1.35V and +0.675V sequece timing	Change PR323 form 0ohm to 1Kohm add CAP 0.1uF connect PR323 to GND	X01
44	38	PWR_Charger(SL9519)	2012-04-10	Power_Jeff	Reduce ADP.J slew rate too slow	Change PC38 form 0.1uF to 0.01uF	X01
45	27	Sensor Fussion / TPM	2012-04-11	Compal_Jay	Remove Pressure Sensor function for PT build	De-pop U653,D96,D97,C1148,C1149 and R1093	X01
46	16	PCH (1/8) SATA,HDA,SPL LPC	2012-04-11	Compal_Jay	Follow buyer suggest modify 32.768 crystal CPN	Modify Y1 and YH1 CPN to SJ10000BM00	X01
47	39	PWR_3_3VALWP/SVALWP-8243	2012-04-11	Power_Jeff	Follow buyer suggest modify 10UF CAP CPN	Modify PC222 CPN to SE000004880	X01

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48	42	PWR_+1.35VP/0.675VSP	2012-04-11	Power_Jeff	Follow buyer suggest, modify 100pf CPN	Modify PC129,PC220 and PC314 P/N to SE071101J8L	X01
49	39	PWR_3.3VALWP/SVALWP-8243	2012-04-11	Power_Jeff	Combine the P/N	Modify PD906,PD907 and PD903 P/N to SC500000Z00	X01
50	44	PWR-CPU_CORE	2012-04-12	Power_Jeff	Modify P/N to Green part	PC708,PC729 change material form SE071101K8L to SE071101J8L	X01
51	27	Sensor Fussion / TPM	2012-04-16	Compal_Jay	Option +3VALW and +RTCVCC for Sensor hub Vbat pin and default is +3VALW.	Add R1101 and R1102 for option +3VALW and +RTCVCC.	X01
52	27	Sensor Fussion / TPM	2012-04-16	Compal_Jay	Follow Intel suggest, pin 4 change from floating to GND.	U638 pin 4 change from floating to GND.	X01
53	29	mSATA / NFC Conn	2012-04-17	Compal_Jay	mSATA don't need +5VS power,remove +5VS power rail from JSATA3 connector.	Remove +5VS power rail	X01
54	24	eDP/ Camera CONN	2012-04-18	Compal_Jay	Add souldion for EMI fix DMIC noise issue	RS37 change to 100-ohm, C1133 pop 10pF and add C1206 pop 10pF.	X01
55	22	PCH (7/8) PWR	2012-04-18	Compal_Jay	Modify P/N to COMMON part H=1.9	Modify CH86 and CH88 P/N to SGA0000170L	X01
56	37	PWR_DCIN / BATT CONN / OTP	2012-04-19	Power_Jeff	IPCC/ VC_IN function support	De-pop PR937 and PR936 change to 0-ohm	X01
57	30	PWR_DCIN / BATT CONN / OTP	2012-04-19	Compal_Jay	Follow ME new connector list X14, modify JUSB2 P/N	Change JUSB2 P/N to ACON_TARAG-9V1391	X01
58	37	PWR_DCIN / BATT CONN / OTP	2012-04-20	Power_Jeff	For fix EMI LX_3V and LX_5V nets cause the boardband noise	Pop PR208,PR209, PC212,PC213	X01
59	35	EC ENE-KB9012	2012-04-20	Compal_Jay	Change FAN to PWM control Add BMON function	1.Change GPIO13 from ACOFF to SYSTEM_FAN_PWM 2.Remove ACOFF PD R1022 3.Change GP39 from VOLUME_UP_SW# to BMON 4.Change GPO3D from EN_DFAN1 to VOLUME_UP_SW#	X01
60	34	TP / FAN	2012-04-20	Compal_Jay	Change FAN to PWM control	Follow Thermal team request, change FAN to PWM control circuit	X01
61	38	PWR_Charger(ISL9519)	2012-04-20	Power_Jeff	Remove ACOFF due to add FAN PWM control and BMON function	Remove ACOFF net and add test PAD	X01
62	39	PWR_3.3VALWP/SVALWP-8243	2012-04-23	Power_Jeff	For B+ drop issue	1. Change PC203,PC204 form 4.7uF to 10uF 2. Add PC1912,PC1913 and PC1917 of XSR 0805 10uF to B+ connect GND 3. De-pop PC210,PC211 4. Add PR957(10Kohm), PR958 (100K ohm), PC1911 (2.2uF) and PD909	X01
63	41	PWR_V1.05S_VCCPP	2012-04-23	Power_Jeff	For B+ drop issue	Change PC502,PC503 form 4.7uF to 10uF	X01
64	42	PWR_+1.35VP/0.675VSP	2012-04-23	Power_Jeff	For B+ drop issue	Change PC300,PC302 form 4.7uF to 10uF	X01
65	42	PWR_+1.35VP/0.675VSP	2012-04-23	Power_Jeff	For consider test efficiency	Connect PR119 +1.35VS change to +1.35V	X01
66	43	PWR_+VCCSAP	2012-04-23	Power_Jeff	For adjustment voltage from 0.8V to 0.85V	Change PR607 form 33K to 100K	X01
67	38	PWR_Charger(ISL9519)	2012-04-23	Power_Jeff	Add Battery Current Sensor function	Add Battery Current Sensor - BMON circuits	X01
68	26	Mini DP CONN	2012-04-23	Compal_Jay	Follow ME new connector list X14, modify JMDP1 P/N	Change JMDP1 P/N to ACON_MAR28-20K1200	X01
69	31	BAT LED	2012-04-24	Compal_Jay	Follow DELL request, modify SW1 P/N	Change SW1 P/N to SN100006U0L	X01
70	38	PWR_Charger(ISL9519)	2012-04-25	Power_Jeff	Disable Reserved circuit for DT mode charger	Remove reserved circuit for DT mode charger	X01
71	37	PWR_DCIN / BATT CONN / OTP	2012-04-25	Power_Jeff	Follow EMI request, add one bead on DC-IN GND pin	Add PL903 on DC-IN GND pin	X01
72	34	TP / FAN	2012-04-25	Compal_Jay	Follow DELL suggest, modify JFAN1 P/N same with W1N8/B connector	Change JFAN1 P/N to SP02000Y500	X01
73	39	PWR_3.3VALWP/SVALWP-8243	2012-04-25	Power_Jeff	Follow power team schematic review result	De-pop PR958	X01
74	42	PWR_+1.35VP/0.675VSP	2012-04-25	Power_Jeff	because 2nd Footprint is big size then main sourcewe suggest modify footprint in PT	PQ1226 change Footprint form AON7212L_DFN8-5 to FDMC76725_MLP8-5	X01
75	30	PWR_DCIN / BATT CONN / OTP	2012-04-25	Compal_Jay	Follow ME new connector list X15, modify JUSB2 P/N	Change JUSB2 P/N from ACON_TARAG-9V1391 to ACON_TARAG-9U1391	X01
76	32	DC/DC Interface	2012-04-26	Compal_Jay	For BBU measurement	Add R894 on +3VALW to +3V_PCH, +5VALW to +5V_PCH	X01
77	29	mSATA / NFC Conn	2012-04-26	Compal_Jay	Follow ME new connector list X15, modify JNFC1 P/N from temp P/N to CPN	Update JNFC1 P/N to SP01001H000 (CIS part)	X01

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78	37	PWR_DCIN / BATT CONN / OTP	2012-04-26	Compal_Jay	reserved power Jump on DC-IN GND pin	Add PJP205 on DC-IN GND pin	X01
79	29	mSATA / NFC Conn	2012-04-27	Compal_Jay	Remove NFC function	De-pop C1134 and R974	X01
80	38	PWR_Charger(ISL9519)	2012-05-02	Power_Jeff	For fix derating issue	Change PR942 1Kohm to 3.3K ohm	X01
81	45	PWR_PROCESSOR DECOUPLING	2012-05-03	Power_Jeff	Main source(SANYO) can't supply so modify to other supplier	Change PC987,PC994,PC1900,PC1901 and PC1903 form SGA00002U00 to SGA00006A00.	X01
82	27	Sensor Fussion / TPM	2012-06-05	Compal_Jay	Follow Intel reference design	Reserved R1104 10 Kohm between USB_PP and uC PB5	X01.1
1	16	PCH (1/8) SATA,HDA,SPL LPC	2012-06-21	Compal_Jay	WINBOND SPI ROM have issue on other project, remove WINBOND from schematic.	Change U48 P/N from SA000039A2L to SA000046400 (EON)	X02
2	20	PCH (5/8) GPIO, CPU, MISC	2012-06-21	Compal_Jay	For DDR3L repair request, add strap pin for CH A and CH B Enable/Disable.	Rserved RH338 and RH339 PD	X02
3	39	PWR_3.3VALWP/SVALWP-8243	2012-06-21	Power_Jeff	For 3.5V can't turn-off in SS state,while system change form AC to DC mode	Change PR958 form de-pop to 1M ohm	X02
4	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR738 from 220kOhm to 30kOhm.	X02
5	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR733,PR705 from 499 Ohm to 100 Ohm.	X02
6	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PC728,PC703 from 680pF to 1000pF.	X02
7	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR748 from 442 Ohm to 470 Ohm.	X02
8	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PC743, PC710 from 0.068uF to 0.047uF.	X02
9	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR750,PR707 from non-pop to 649 Ohm.	X02
10	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PC746,PC712 from non-pop to 0.01uF.	X02
11	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PC741 from 0.01uF to non-pop.	X02
12	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR703 from 220kOhm to 44.2k Ohm.	X02
13	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR708 from 137kOhm to 33.2kOhm.	X02
14	44	PWR-CPU_CORE	2012-06-21	Power_Jeff	Following FAE test result and modify component	Change the PR712 from 392 Ohm to 412 Ohm.	X02
15	38	PWR_Charger(ISL9519)	2012-06-21	Power_Jeff	Follow Erp 6 spec (low power mode)	Change PR28 51.1Kohm to 68kohm	X02
16	44	PWR-CPU_CORE	2012-06-22	Power_Jeff	MOS temperature is not meet Dell spec	Change PQ1217,PQ1218 form S800000V800 to S800000XE0L	X02
17	42	PWR_+1.35VP/0.675VSP	2012-06-22	Power_Jeff	Because unstable of phase waveform	Change PL1210 form 2.2UH to 1UH	X02
18	27	Sensor Fussion / TPM	2012-06-22	Compal_Jay	Follow Intel DG V080 and double confirm with Intel	Change R1094 to 1M ohm and add R1105,R1106 and C1207	X02
19	27	Sensor Fussion / TPM	2012-06-22	Compal_Jay	Follow Intel DG V080 and double confirm with Intel	Add R1107 on U638 pin 1	X02
20	27	Sensor Fussion / TPM	2012-06-22	Compal_Jay	Follow Intel DG V080 and double confirm with Intel	De-pop R817 and change R1104 to 1.5K ohm (pop)	X02
21	27	Sensor Fussion / TPM	2012-06-22	Compal_Jay	Follow Intel DG V080 and double confirm with Intel	Contect U636 F6 to U637.5 and U636.E4 to U637.4	X02
22	27	Sensor Fussion / TPM	2012-06-22	Compal_Jay	Follow Intel suggest	Change U636 P/N for SA00004TV0 (STM32F103RDY6TR) to SA00005P20(STM32F103RCY6TR)	X02
23	35	EC ENE-KB9012	2012-06-22	Compal_Jay	Follow EC suggest	Follow EC suggest, change TABLET_MODE from PU to PD.	X02
24	31	BAT LED	2012-06-22	Compal_Jay	Follow factory suggest, change LED to ESD protest LED	Change LED P/N form SC500007G00 to SC50000D70L	X02
25	06	CPU(2/6) PMXDP,CLK53,PLT	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RC49, RC53, RC56, RC11 to short PAD type	X02
26	09	CPU(5/6) PWR,BYPASS	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RH280, RC92, RC96, RC98, RC99 to short PAD type	X02
27	16	PCH (1/8) SATA,HDA,SPL LPC	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RH255 to short PAD type	X02
28	18	PCH (3/8) DMIFDLP,GMX,DP	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RH273, RH130, RH131, RH133, RH297, RH293,RH137, RH132 to short PAD type	X02
29	19	PCH (4/8) PCL USB, NVRAM	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RH336 to short PAD type	X02
30	21	PCH (6/8) PWR	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RH207, RH210, RH211 to short PAD type	X02

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31	22	PCH (7/8) PWR	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RH219, RH230, RH247, RH244, RH292, RH233 to short PAD type	X02
32	24	eDP/ Camera CONN	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change R983, R984, R538 to short PAD type	X02
33	26	Mini DP CONN	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change RV8 to short PAD type	X02
34	27	Sensor Fusion / TPM	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change R1090 to short PAD type	X02
35	28	WLAN / WiGig / BT	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change R1017, R1012, R1013, R1014, R1015, R1016 to short PAD type	X02
36	32	DC/DC Interface	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change R1031 to short PAD type	X02
37	35	EC ENE-KB9012	2012-06-25	Compal_Jay	Change 0 ohm resistors to short PAD type	Change R216, R921, R249, R250, R253, R926, R931, R933, R934, R982, R925, R228 to short PAD type	X02
38	39	PWR_3_3VALWP/SVALWP-8243	2012-06-26	Power_Jeff	OCp protection over Dell space	Change PR218 from 43kohm to 39kohm and PR216 from 45.3K to 37.4kohm	X02
39	42	PWR_+1.35VP/0.675VSP	2012-06-26	Power_Jeff	OCp protection over Dell space	Change PR301 from 7.68Kohm to 6.98Kohm	X02
40	11	DDRIII Channel_A Lower	2012-06-26	Compal_Jay	For cost down solution, add SPD code into BIOS and remove SPD ROM.	De-pop UD17, RD39, RD40 and CD127	X02
41	13	DDRIII Channel_B Lower	2012-06-26	Compal_Jay	For cost down solution, add SPD code into BIOS and remove SPD ROM.	De-pop UD18, RD41, RD42 and CD128	X02
42	38	PWR_Charger(ISL9519)	2012-06-27	Power_Jeff	Reserve Eip Lot 6 solution circuit into ST	Reserve PR964, PR965, PR966, PR967, PR968, PC1918 and PQ1228	X02
43	38	PWR_Charger(ISL9519)	2012-06-27	Power_Jeff	Because ISL9519 support, so de-pop component	De-pop component to PQ1227, PQ7, PR942, PR943, PR41	X02
44	20	PCH (5/8) GPIO, CPU, MISC	2012-06-28	Compal_Jay	Modify GPIO name for TPM optional	Modify GPIO PCH_GPIO16 to TPM_DEI	X02
45	20	PCH (5/8) GPIO, CPU, MISC	2012-06-28	Compal_Jay	Modify GPIO name for DDR3L strap	Modify GPIO PCH_GPIO17 to MEM_CHA_EN and PCH_GPIO22 to MEM_CHB_EN	X02
46	20	PCH (5/8) GPIO, CPU, MISC	2012-06-28	Compal_Jay	Modify GPIO name for sensor hub PWRGATE	Modify GPIO PCH_GPIO35 to SH_PWR_CNTRL	X02
47	20	PCH (5/8) GPIO, CPU, MISC	2012-06-28	Compal_Jay	Modify GPIO name for sensor hub uC Dfu mode enable	Modify GPIO PCH_GPIO68 to SH_DFU_EN#	X02
48	16	PCH (1/8) SATA, HDA, SPL LPC	2012-06-28	Compal_Jay	Follow EMI request, modify HDA_BIT_CLK R/C value	Modify RH27 from 33 ohm to 47 ohm and CH117 from 10p to 22p	X02
49	35	EC ENE-KB9012	2012-06-29	Compal_Jay	M/B side power SW interference with cable reoting	De-pop SW2	X02
50	38	PWR_Charger(ISL9519)	2012-06-29	Power_Jeff	For cost down solution	De-pop BMON circuit	X02
51	37	PWR_DCIN / BATT CONN / OTP	2012-06-29	Compal_Jay	Follow Inter new revision check list suggest	Reserve PR905 10K ohm PD on PCH_DPWROK	X02
52	30	USB 3.0 IO CONN	2012-07-02	Compal_Jay	Follow connector list 2012-06-29	Modify connector Mfr. P/N form TARAG-9U1391 to TARAG-9R1391	X02
53	33	SCREW/KB/RTC	2012-07-02	Compal_Jay	Follow connector list 2012-06-29	Modify JKB1 Mfr. P/N from 50699-03041-001 to 50699-03041-P01	X02
54	33	SCREW/KB/RTC	2012-07-02	Compal_Jay	Follow connector list 2012-06-29	Modify JBL1 P/N from LTCX003N800 to SP01001HD00	X02
55	37	PWR_DCIN / BATT CONN / OTP	2012-07-02	Compal_Jay	Follow connector list 2012-06-29	Modify JBATT9 Mfr. P/N from GS73091-10272-7H to GS73091-10272M-7H	X02
56	27	Sensor Fusion / TPM	2012-07-05	Compal_Jay	Follow HWDG 0.85 update	change R1107 and R1091 to 0 ohm	X02
57	27	Sensor Fusion / TPM	2012-07-05	Compal_Jay	Follow HWDG 0.85 update	De-pop R1104	X02
58	39	PWR_3_3VALWP/SVALWP-8243	2012-07-05	Power_Jeff	For 3/5V turn-off issue	Reserve PC1919 and PC1920 (de-pop)	X02
59	35	EC ENE-KB9012	2012-07-05	Compal_Jay	PLT_RST# double PD	De-pop R929	X02
60	16	PCH (1/8) SATA, HDA, SPL LPC	2012-07-05	Compal_Jay	Follow DFB review suggest	Change Y1/YH1 footprint from Y_CM31532768DZFT_2P to Y_FC-135_2P	X02
61	39	PWR_3_3VALWP/SVALWP-8243	2012-07-06	Power_Jeff	NEC can't support SGA00004H00 this part	Change PC210, PC214, PC211 and PC224 from SGA00004H00 to SGA00002N8L	X02
62	39	PWR_3_3VALWP/SVALWP-8243	2012-07-06	Compal_Jay	For fix OTP issue	Add PR969 link EC_ON and N_SV_001 and pop PC217 (0.1u) and add PR970(1M ohm) PD.	X02
63	27	Sensor Fusion / TPM	2012-07-06	Compal_Jay	Delete PRESSURE sensor schematic for SSD nut space	Re-move Pressure sensor circuit and add test pad	X02

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64	32	DC/DC Interface	2012-07-06	Compal_Jay	For meet LG panel power sequence	Change C1165 and C1143 from 10uF to 1uF and C1164 form 470P to 1000P	X02
	24	eDP/ Camera CONN					
65	28	WLAN / WiGig / BT	2012-07-06	Compal_Jay	Reserve RF switcher circuit	Reserve RF switcher circuit	X02
	20	PCH (5/8) GPIO, CPU, MISC				Modify PCH_GPIO48 to RFSW_VCONT1 and PCH_GPIO49 to RFSW_VCONT2	
66	29	mSATA / NFC Conn	2012-07-06	Compal_Jay	Delete NFC circuit	Delete NFC circuit	X02
	17	PCH (2/8) PCIE, SMBUS, CLK				Move R1100 from page 29 to page 17	
67	39	PWR_3.3VALWP/SVALWP-8243	2012-07-10	Compal_Jay	For fix OTP issue	Change PC217 to 1uF, PR938 to 10K ohm and add PR971 (1K ohm)	X02
68	17	PCH (2/8) PCIE, SMBUS, CLK	2012-07-11	Compal_Jay	Follow crystal EA test result	Change CH23 and CH24 from 12P to 15P	X02
69	16	PCH (1/8) SATA,HDA,SPL LPC	2012-07-11	Compal_Jay	Follow crystal EA test result	Change CH2 and CH3 from 22P to 18P	X02
70	24	eDP/ Camera CONN	2012-07-17	Compal_Jay	Prevent Q70 can't turn-off potential issue while battery work in low capacity	Change R536 from 1M ohm to 100K ohm	X02
71	27	Sensor Fussion / TPM	2012-07-17	Compal_Jay	Follow INTEL schematic review result	Pop R817 1.5K ohm	X02
72	27	Sensor Fussion / TPM	2012-07-17	Compal_Jay	Follow ST suggest, change supplier P/N for QAZA0 only	Follow ST suggest, change U636 P/N for SA00005P20L (STM32F103RCY6TR1) to SA00005P21L (STM32F103RCY6TRC117)	X02
73	35	EC ENE-KB9012	2012-07-20	Compal_Jay	Modify board ID setting	Modify R225 form 18K ohm to 33K ohm	X02
74	35	EC ENE-KB9012	2012-07-23	Compal_Jay	Modify TABLET_MODE PU and PD valu setting	Modify R980 form 10K ohm to 100K ohm (WIN8/B R1 form 1K ohm to 10K ohm)	X02
1	35	EC ENE-KB9012	2012-08-20	Compal_Jay	Modify board ID setting	Modify R225 form 33K ohm to 56K ohm	A00
2	16	PCH (1/8) SATA,HDA,SPL LPC	2012-08-20	Compal_Jay	Follow DFB review result	Modify YH1 footprint	A00
3	27	Sensor Fussion / TPM	2012-08-20	Compal_Jay	Follow DFB review result	Modify Y1 footprint	A00
4	37	PWR_DCIN / BATT CONN / OTP	2012-08-20	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR911 and PR918 to short PAD	A00
5	38	PWR_Charger(ISL9519)	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR30,PR46,PR954,PR955,PR956 to short PAD	A00
6	39	PWR_3.3VALWP/SVALWP-8243	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR219,PR512,PR513,PR515 to short PAD	A00
7	41	PWR_V1.05S_VCCPP	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR508,PR509 to short PAD	A00
8	43	PWR_VCCSAP	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR610, PR611 to short PAD	A00
9	44	PWR_CPU_CORE	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR720,PR721,PR736,PR722 to short PAD	A00
10	6	CPU(2/6) PMXDP,CLK53,PLT	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify RC145 to short PAD	A00
11	9	CPU(5/6) PWR,BYPASS	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify RC109 to short PAD	A00
12	18	PCH (3/8) DMLFDLPM,GF,XDP	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify RH313, RH309, RH310 to short PAD	A00
13	22	PCH (3/8) DMLFDLPM,GF,XDP	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify RH312 to short PAD	A00
14	24	eDP/ Camera CONN	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify R1084, R1010, R1011 to short PAD	A00
15	27	Sensor Fussion / TPM	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify R819 to short PAD	A00
16	28	WLAN / WiGig / BT	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify R741, R742, R728 to short PAD and de-pop R729	A00
17	32	DC/DC Interface	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify RC107 to short PAD	A00
18	35	EC ENE-KB9012	2012-08-21	Compal_Jay	Change 0 ohm resistors to short PAD type	Modify R265 to short PAD	A00
19	18	PCH (3/8) DMLFDLPM,GF,XDP	2012-08-21	Compal_Jay	VGATE prevent voltage divider less than 3V	Change RH272 from 10K to 47K	A00
20	40	PWR_1.8VSP/1.5VSP	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR517,PR518 to short PAD	A00
21	42	PWR_+1.35VP/0.675VSP	2012-08-21	Power_Jeff	Change 0 ohm resistors to short PAD type	Modify PR521 and PR119to short PAD	A00

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22	42	PWR_+1.35VP/0.675VSP	2012-08-22	Power_Jeff	Follow Green specification change component	Change PR304 form 8.2k 5% to 8.2K 1%	A00
23	38 43	PWR_Charger(ISL9519) PWR_+VCCSAP	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PC38 from 0.01U_0402_25V7K to 0.01U_0402_16V7K Change PC618 from 0.01U_0402_25V7K to 0.01U_0402_16V7K	A00
24	38 43	PWR_Charger(ISL9519) PWR_+VCCSAP	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PC37 from SE102104K00 to SE102104K8L Change PC606 from SE102104K00 to SE102104K8L	A00
25	20	PCH (5/8) GPIO, CPU, MISC	2012-08-22	Compal_Jay	For DDR3L chip repair request	Change RH338 and RH339 from 0603 pad to short pad	A00
26	37	PWR_DGIN / BATT CONN / OTP	2012-08-22	Power_Jeff	Follow Green specification change component	Change PQ903 form SB906100210 to SB90610021L	A00
27	38 43	PWR_Charger(ISL9519) PWR_+VCCSAP	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PC22 from SE095224K00 to SE095224K8L Change PC616 from SE095224K00 to SE095224K8L	A00
28	40 45	PWR_1.8VSP/1.5VSP PWR_PROCESSOR DECOUPLING	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PC400 and PC410 from SE000000110 to SE00000110L Change PC400,PC410,PC850,PC851,PC852,PC853,PC854,PC855,PC858,PC859,PC860,PC861,PC862,PC890,PC891,PC892,PC893,PC894,PC913,PC916 from SE000000110 to SE00000110L	A00
29	43	PWR_+VCCSAP	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PR608 from SD034100080 to SD03410008L	A00
30	38 39 40	PWR_Charger(ISL9519) PWR_3.3VALWP/SVALWP-8243 PWR_1.8VSP/1.5VSP	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PR26 from SD001470880 to SD01147088L Change PR208 and PR209 from SD001470880 to SD01147088L Change PR400 and PR406 from SD001470880 to SD01147088L	A00
31	38	PWR_Charger(ISL9519)	2012-08-22	Power_Jeff	Combine P/N for BPM request	Change PC39 from SE068102J80 to SE074102K8L	A00
32	31	BAT LED	2012-08-23	Compal_Jay	BATT_LED#_LVx PU power rail change to +3VALW because of EC those pin are not 5V tolerance	Change BATT_LED#_LVx PU power rail from +5VALW to +3VALW	A00
33	39	PWR_3.3VALWP/SVALWP-8243	2012-08-23	Power_Jeff	Follow DFB review result	Re-move PL402	A00
34	41	PWR_V105S_VCCPP	2012-08-23	Power_Jeff	Follow DFB review result	Re-move PL405	A00
35	42	PWR_+1.35VP/0.675VSP	2012-08-23	Power_Jeff	Follow DFB review result	Re-move PL406	A00
36	44	PWR-CPU_CORE	2012-08-23	Power_Jeff	Follow DFB review result	Re-move PL700 and PL702	A00
37	38	PWR_Charger(ISL9519)	2012-08-23	Power_Jeff	Follow DFB review result	Re-move PL403 and PL404	A00
38	30	USB 3.0 IO CONN	2012-08-27	Compal_Jay	Follow connector list 0810_X15	Modify JUSB1 connector mfr. P/N from USB014-107CRL-TW to USB014-107CRL-TWD (remove mayla only)	A00
39	33	SCREWH/KB/RTC	2012-08-27	Compal_Jay	Follow connector list 0810_X15	Modify JRTC1 P/N from SP020009Z0L to SP02000U800	A00
40	33	SCREWH/KB/RTC	2012-08-27	Compal_Jay	Follow connector list 0810_X15	Modify JKB1 connector mfr. P/N from 50699-03041-P01 to 50699-03001-P01 (remove mayla only)	A00
41	25	IOL Conn	2012-08-31	Compal_Jay	Follow EMI test request	Modify LH9 P/N to SM01000LJ0L	A00
42	24	eDP/ Camera CONN	2012-09-10	Compal_Jay	For fix panel adjusting on legacy and UEFI mode	Pop D92 for PCH_JNV_PWM control	A00

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